

DESCRIPTION

**OXIDE SEMICONDUCTOR STACKED FILM AND SEMICONDUCTOR
DEVICE**

5

TECHNICAL FIELD

[0001]

The present invention relates to a method for manufacturing a semiconductor device including an oxide semiconductor stacked film and a field-effect transistor.

10

BACKGROUND ART

[0002]

Transistors used for most flat panel displays typified by a liquid crystal display device and a light-emitting display device are formed using silicon semiconductors such as amorphous silicon, single crystal silicon, and polycrystalline silicon provided over glass substrates. Further, transistors formed using such silicon semiconductors are used in integrated circuits (ICs) and the like.

15

[0003]

In recent years, attention has been drawn to a technique in which, instead of a silicon semiconductor, a metal oxide exhibiting semiconductor characteristics is used for transistors. Note that in this specification and the like, a metal oxide exhibiting semiconductor characteristics is referred to as an oxide semiconductor.

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[0004]

For example, a technique is disclosed in which a transistor is manufactured using zinc oxide or an In-Ga-Zn-based oxide as an oxide semiconductor and the transistor is used as a switching element or the like of a pixel of a display device (see Patent Documents 1 and 2).

25

[0005]

Further, in Non-Patent Document 1, it has been reported that an amorphous In-Ga-Zn-O film has an extremely high density of defect states higher than or equal to $1 \times 10^{20}/\text{cm}^3$ and the defect states are reduced by almost half by heat treatment.

30

[Reference]

[Non-Patent Document]

[0006]

[Non-Patent Document 1] Kamiya, Nomura, and Hosono, "Carrier Transport Properties and Electronic Structures of Amorphous Oxide Semiconductors: The present status",
5 *KOTAI BUTSURI (SOLID STATE PHYSICS)*, 2009, Vol. 44, pp. 621-633

[Patent Document]

[0007]

[Patent Document 1] Japanese Published Patent Application No. 2007-123861

[Patent Document 2] Japanese Published Patent Application No. 2007-096055

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DISCLOSURE OF INVENTION

[0008]

A transistor using an oxide semiconductor has a problem in that the electrical characteristics, typically, the threshold voltages, are varied with time or through the gate
15 bias temperature (GBT) stress test. For example, when a transistor uses the oxide semiconductor having the density of defect states described in Non-Patent Document 1, the electrical characteristics such as the threshold voltage of the transistor may be varied.

[0009]

20 Such a variation in electrical characteristics of a transistor causes a reduction in reliability of a semiconductor device including the transistor.

[0010]

In view of the above problem, an object of one embodiment of the present invention is to provide an oxide semiconductor stacked film which does not easily cause
25 a variation in electrical characteristics of a transistor and has high stability. Another object is to provide a transistor which includes the oxide semiconductor stacked film in its channel formation region and has stable electrical characteristics. Another object is to improve reliability of a semiconductor device including the transistor.

[0011]

30 One embodiment of the present invention is an oxide semiconductor stacked film in which the absorption coefficient due to localized states measured by the CPM is lower than or equal to $3 \times 10^{-3}/\text{cm}$, preferably lower than or equal to $3 \times 10^{-4}/\text{cm}$ in an

energy range of 1.5 eV to 2.3 eV.

[0012]

One embodiment of the present invention is an oxide semiconductor stacked film including a first oxide semiconductor layer, a second oxide semiconductor layer, and a third oxide semiconductor layer which are sequentially stacked and each of which contains indium, gallium, and zinc. The content percentage of indium in the second oxide semiconductor layer is higher than that in the first oxide semiconductor layer and the third oxide semiconductor layer. The absorption coefficient of the oxide semiconductor stacked film due to localized states, which is measured by the CPM, is lower than or equal to $3 \times 10^{-3}/\text{cm}$ in an energy range of 1.5 eV to 2.3 eV.

[0013]

Further, another embodiment of the present invention is a semiconductor device including a gate electrode layer, a gate insulating film over the gate electrode layer, an oxide semiconductor stacked film overlapping with the gate electrode layer with the gate insulating film interposed therebetween, and a pair of electrode layers in contact with the oxide semiconductor stacked film. The oxide semiconductor stacked film includes a first oxide semiconductor layer, a second oxide semiconductor layer, and a third oxide semiconductor layer which are sequentially stacked and each of which contains indium, gallium, and zinc. The content percentage of indium in the second oxide semiconductor layer is higher than that in the first oxide semiconductor layer and the third oxide semiconductor layer. The absorption coefficient of the oxide semiconductor stacked film due to localized states, which is measured by the CPM, is lower than or equal to $3 \times 10^{-3}/\text{cm}$ in an energy range of 1.5 eV to 2.3 eV.

[0014]

In the above structure, it is preferable that an oxide insulating film be further provided over the pair of electrode layers and the oxide semiconductor stacked film.

[0015]

A semiconductor device of one embodiment of the present invention includes a transistor using an oxide semiconductor stacked film or a circuit including the transistor. For example, an electronic device which includes, as a component, a semiconductor integrated circuit including an LSI, a CPU, a power device mounted in a power circuit, a

memory, a thyristor, a converter, an image sensor, or the like; an electro-optical device typified by a liquid crystal display panel; or a light-emitting display device including a light-emitting element is also included in the category of the semiconductor device.

[0016]

5 With one embodiment of the present invention, an oxide semiconductor stacked film which does not easily cause a variation in electrical characteristics of a transistor and has high stability can be provided. Further, a transistor which includes the oxide semiconductor stacked film in its channel formation region and has stable electrical characteristics can be provided. Furthermore, reliability of a semiconductor device
10 including the transistor can be improved.

BRIEF DESCRIPTION OF DRAWINGS

[0017]

In the accompanying drawings:

15 FIGS. 1A and 1B each illustrate an oxide semiconductor stacked film;

 FIGS. 2A to 2C illustrate oxide semiconductor stacked films having a single-layer structure, a two-layer structure, and a three-layer structure, respectively;

 FIG. 3 illustrates a CPM measurement apparatus;

 FIGS. 4A to 4C are a plan view and cross-sectional views illustrating a
20 semiconductor device;

 FIGS. 5A and 5B are cross-sectional views each illustrating a semiconductor device;

 FIGS. 6A and 6B are a cross-sectional view and an energy band diagram of an oxide semiconductor stacked film having a single-layer structure;

25 FIGS. 7A and 7B are a cross-sectional view and an energy band diagram of an oxide semiconductor stacked film having a three-layer structure;

 FIGS. 8A to 8E are cross-sectional views illustrating a method for manufacturing a semiconductor device;

 FIGS. 9A to 9D are cross-sectional views each illustrating a semiconductor
30 device;

 FIGS. 10A to 10D are cross-sectional views each illustrating a semiconductor device;

FIGS. 11A to 11C each illustrate an electronic appliance;

FIGS. 12A to 12C illustrate an electronic appliance;

FIGS. 13A and 13B are cross-sectional views illustrating a sample A and a sample B;

5 FIGS. 14A and 14B show results of CPM measurement of a sample A;

FIGS. 15A and 15B show results of CPM measurement of a sample B;

FIGS. 16A to 16D illustrate a method for manufacturing a transistor;

FIGS. 17A and 17B each show V_g - I_d characteristics of a transistor included in a sample C;

10 FIGS. 18A and 18B each show V_g - I_d characteristics of a transistor included in a sample D; and

FIGS. 19A and 19B each show V_g - I_d characteristics of a transistor included in a sample E.

15 BEST MODE FOR CARRYING OUT THE INVENTION

[0018]

Hereinafter, embodiments of the invention disclosed in this specification and the like are described in detail with reference to the accompanying drawings. However, the invention disclosed in this specification and the like is not limited to the description
20 below, and it is easily understood by those skilled in the art that modes and details disclosed herein can be modified in various ways. Therefore, the invention disclosed in this specification and the like is not construed as being limited to the descriptions of the following embodiments. Note that the ordinal numbers such as “first” and “second” in this specification are used for convenience and do not denote the order of
25 steps and the stacking order of layers. In addition, the ordinal numbers in this specification do not denote particular names which specify the present invention.

[0019]

(Embodiment 1)

In this embodiment, an oxide semiconductor stacked film of one embodiment
30 of the present invention is described with reference to FIGS. 1A and 1B.

[0020]

FIG. 1A illustrates an oxide semiconductor stacked film 101 provided over a

substrate 100. The oxide semiconductor stacked film 101 includes a plurality of oxide semiconductor layers, and for example, a first oxide semiconductor layer 101a, a second oxide semiconductor layer 101b, and a third oxide semiconductor layer 101c are sequentially stacked in the oxide semiconductor stacked film 101.

5 [0021]

The oxide semiconductor layers 101a to 101c each include indium, gallium, and zinc at different atomic ratios. Among the oxide semiconductor layers 101a to 101c, for example, the content percentage of indium in the second oxide semiconductor layer 101b is preferably higher than that in the first oxide semiconductor layer 101a and
10 is preferably higher than that in the third oxide semiconductor layer 101c.

[0022]

Furthermore, in the second oxide semiconductor layer 101b, the content percentage of indium is preferably higher than that of gallium.

[0023]

15 Note that the first oxide semiconductor layer 101a and the third oxide semiconductor layer 101c may have the same atomic ratio or different atomic ratios.

[0024]

For example, the first oxide semiconductor layer 101a has an atomic ratio of In:Ga:Zn = 1:3:2, the second oxide semiconductor layer 101b has an atomic ratio of
20 In:Ga:Zn = 1:1:1, and the third oxide semiconductor layer 101c has an atomic ratio of In:Ga:Zn = 1:3:2. Alternatively, the first oxide semiconductor layer 101a has an atomic ratio of In:Ga:Zn = 1:3:2, the second oxide semiconductor layer 101b has an atomic ratio of In:Ga:Zn = 3:1:2, and the third oxide semiconductor layer 101c has an atomic ratio of In:Ga:Zn = 1:1:1. Note that a proportion of each atom in the atomic
25 ratio of the oxide semiconductor layer varies within a range of $\pm 20\%$, or within a range of $\pm 10\%$ as an error.

[0025]

The second oxide semiconductor layer 101b may have a stacked-layer structure. In FIG. 1B, the second oxide semiconductor layer 101b including an oxide
30 semiconductor layer 101b1 and an oxide semiconductor layer 101b2 is illustrated. Note that the second oxide semiconductor layer 101b may have three layers or more.

[0026]

At this time, the content percentage of indium in the oxide semiconductor layers 101b1 and 101b2 is preferably higher than that in the oxide semiconductor layer 101a and is preferably higher than that in the oxide semiconductor layer 101c.

5 [0027]

For example, it is preferable that the first oxide semiconductor layer 101a have an atomic ratio of In:Ga:Zn = 1:3:2, the oxide semiconductor layer 101b1 in the second oxide semiconductor layer 101b have an atomic ratio of In:Ga:Zn = 3:1:2, the oxide semiconductor layer 101b2 in the second oxide semiconductor layer 101b have an atomic ratio of In:Ga:Zn = 1:1:1, and the third oxide semiconductor layer 101c have an atomic ratio of In:Ga:Zn = 1:3:2. Note that a proportion of each atom in the atomic ratio of the oxide semiconductor layer varies within a range of $\pm 20\%$, or within a range of $\pm 10\%$ as an error.

[0028]

15 As the proportion of indium becomes higher in a metal oxide included in an oxide semiconductor, the conductivity of the metal oxide increases. For example, in the case where the content percentage of indium in the second oxide semiconductor layer 101b is higher than that in the first oxide semiconductor layer 101a and the third oxide semiconductor layer 101c, the conductivity σ_2 of the second oxide semiconductor layer 101b can be made higher than the conductivity σ_1 of the first oxide semiconductor layer 101a and the conductivity σ_3 of the third oxide semiconductor layer 101c.

[0029]

The conductivity σ_2 is preferably higher than the conductivity σ_1 and the conductivity σ_3 by 1×10^3 S/cm or more, more preferably by 1×10^5 S/cm or more.

25 [0030]

Here, the effect of using the oxide semiconductor stacked film of one embodiment of the present invention is described with reference to FIGS. 2A to 2C.

[0031]

30 In a transistor using an oxide semiconductor, oxygen vacancies in an oxide semiconductor layer cause defects of electrical characteristics of the transistor. Thus, the oxygen vacancies in the oxide semiconductor layer need to be reduced. The

oxygen vacancies in the oxide semiconductor layer can be reduced, for example, by adding oxygen to the oxide semiconductor layer or supplying oxygen from an insulating film in contact with the oxide semiconductor layer.

[0032]

5 However, in the case where the insulating film in contact with the oxide semiconductor layer is formed using an element which is different from the element included in the oxide semiconductor layer, oxygen vacancies are easily formed at an interface between the oxide semiconductor layer and the insulating film. The oxygen vacancies which are formed between the oxide semiconductor layer and the insulating
10 film are difficult to reduce by the above process.

[0033]

The oxygen vacancies included in the oxide semiconductor layer appear as the localized states in a deep energy level of the energy gap of the oxide semiconductor.

[0034]

15 For example, in the case where the oxide semiconductor layer has a single-layer structure as illustrated in FIG. 2A, oxygen vacancies are easily formed at an interface between an oxide semiconductor layer 111 and an insulating film 121 or an interface between the oxide semiconductor layer 111 and an insulating film 122. When voltage is applied from the insulating film 122 side, carriers flow in the interface
20 between the oxide semiconductor layer 111 and the insulating film 122. In this case, when localized states due to the oxygen vacancies exist at the interface between the oxide semiconductor layer 111 and the insulating film 122, the carriers are trapped in the localized states, so that the reliability of the transistor is decreased.

[0035]

25 Further, in the case where the oxide semiconductor layer has a two-layer structure as illustrated in FIG. 2B, oxygen vacancies are easily formed at an interface between an oxide semiconductor layer 112a and the insulating film 121 or an interface between an oxide semiconductor layer 112b and the insulating film 122. When voltage is applied from the insulating film 122 side, carriers flow in the interface
30 between the oxide semiconductor layer 112b and the insulating film 122. In this case, when localized states due to the oxygen vacancies exist at the interface between the oxide semiconductor layer 112b and the insulating film 122, the carriers are trapped in

the localized states, so that the reliability of the transistor is decreased.

[0036]

Thus, as illustrated in FIG. 2C, the oxide semiconductor layer is made to have a three-layer structure, and the conductivity of an oxide semiconductor layer 113b is made
5 higher than that of an oxide semiconductor layer 113a and an oxide semiconductor layer 113c. With the above structure, even when voltage is applied from the insulating film 122 side, carriers do not flow in an interface between the oxide semiconductor layer 113c and the insulating film 122 but flow in an interface between the oxide semiconductor layer 113b and the oxide semiconductor layer 113c. Further, the oxide
10 semiconductor layer 113b and the oxide semiconductor layer 113c include the same constituent elements with different atomic ratios. Thus, the amount of oxygen vacancies at the interface between the oxide semiconductor layer 113b and the oxide semiconductor layer 113c is reduced. As a result, even if carriers flow in the interface between the oxide semiconductor layer 113b and the oxide semiconductor layer 113c,
15 the influence of the localized states due to the oxygen vacancies can be reduced.

[0037]

Defects of the oxide semiconductor (oxygen vacancies) can be measured by a constant photocurrent method (CPM), for example. The CPM measurement is carried out in such a manner that the amount of light with which a surface of a sample between
20 terminals is irradiated is adjusted in the state where voltage is applied between two electrodes included in the sample so that a photocurrent value is kept constant, and the absorption coefficient is derived from the amount of the irradiation light in each wavelength. In the CPM measurement, when the sample has a defect, the absorption coefficient of energy which corresponds to a level at which the defect exists (calculated
25 from a wavelength) is increased. The increase in the absorption coefficient is multiplied by a constant, whereby a density of states (hereinafter, also referred to as DOS) of the sample can be obtained.

[0038]

FIG. 3 illustrates a schematic view of a CPM measurement apparatus. In FIG.
30 3, light paths are denoted by arrows and wirings and the like are denoted by solid lines.

[0039]

The CPM measurement apparatus includes a lamp 201 which is a light source,

a monochromator 202 which extracts light only in a narrow wavelength range from light in a broad wavelength range, a filter 203 which attenuates light passing through the monochromator 202, a beam splitter 204 which transmits and reflects the light attenuated by the monochromator 202, a photodiode 205 which converts light into
5 current, a lock-in amplifier 209 which measures current, and a calculator 208 which estimates the amount of the irradiation light from the measured current.

[0040]

Further, a sample 210 in FIG. 3 is the oxide semiconductor stacked film 101 in FIGS. 1A and 1B. Electrodes 211a and 211b for measurement are provided on the
10 oxide semiconductor stacked film 101. The electrodes 211a and 211b may be formed to have a single-layer structure or a stacked-layer structure using one or more of the following materials: Al, Ti, Cr, Co, Ni, Cu, Y, Zr, Mo, Ag, Ta, W, Pt, and Au, a nitride of any of these elements, an oxide of any of these elements, and an alloy of any of these elements. Alternatively, a transparent conductive film containing plural kinds of
15 materials selected from Si, Ti, Ni, Cu, Zn, Ga, In, and Sn may be used. It is preferable to select a material which does not form an insulating film at the interface between the electrode 211a and the oxide semiconductor stacked film 101 and the interface between the electrode 211b and the oxide semiconductor stacked film 101.

[0041]

20 The electrode 211b is connected to a direct-current power source 206 through a resistor, and a photocurrent value can be measured by a lock-in amplifier 207 connected to the resistor in parallel.

[0042]

As the lamp 201, a xenon lamp, a mercury lamp, a halogen lamp, or the like
25 can be used, for example. Any one of these lamps or a combination thereof may be used. The xenon lamp is preferable because it allows measurement to be carried out in the range of 1.5 eV to 4.0 eV.

[0043]

As the filter 203, a neutral density (ND) filter, a wedge filter, a cut filter, or the
30 like can be used. A cut filter is an optical filter which has a function of transmitting light in a specific wavelength range and attenuating light in the other wavelength range. Further, by using the above filters in combination, the amount of the irradiation light or

the irradiation wavelength can be controlled more effectively. Note that the filter 203 is not necessarily provided.

[0044]

The lock-in amplifier 207 and the lock-in amplifier 209 each have a function of
5 amplifying, detecting, and outputting a signal with a specific frequency of the inputted signals. Thus, the influence of noise or the like is reduced and the signal can be detected in a high sensitivity.

[0045]

The light emitted from the lamp 201 enters the monochromator 202, whereby
10 light only in a narrow wavelength range is extracted from the light in a broad wavelength range. The light passing through the monochromator 202 is attenuated by entering the filter 203. The attenuated light is emitted to the beam splitter 204, whereby the transmitted light is emitted to the sample 210 and the reflected light is emitted to the photodiode 205. Note that the transmitted light and the reflected light
15 are not necessarily emitted to the sample 210 and the photodiode 205, respectively, and can be reversed.

[0046]

The emitted light is converted into current by the photodiode 205. After that, the current is measured by the lock-in amplifier 209, and the amount of the irradiation
20 light can be estimated by the calculator 208. Further, the photocurrent value is measured from the light emitted to the sample 210 by the lock-in amplifier 207. The obtained photocurrent value is fed back to the filter 203 by the calculator 208. When the photocurrent value is too high, the transmittance of the filter 203 is decreased to reduce the amount of the irradiation light. When the photocurrent value is too low, the
25 transmittance of the filter 203 is increased to increase the amount of the irradiation light.

[0047]

The absorption coefficient which is called an urbach tail due to the band tail is removed from a curve of the absorption coefficient obtained by the CPM measurement, whereby the absorption coefficient due to the localized states can be calculated from the
30 following formula.

[0048]

[FORMULA 1]

$$\int \frac{\alpha(E) - \alpha_u}{E} dE$$

[0049]

Here, $\alpha(E)$ indicates the absorption coefficient at each energy level and α_u indicates the absorption coefficient due to the urbach tail.

5 [0050]

The oxide semiconductor layers are stacked as illustrated in FIGS. 1A and 1B, whereby the absorption coefficient due to the localized states measured by the CPM can be made lower than or equal to $3 \times 10^{-3}/\text{cm}$, preferably lower than or equal to $3 \times 10^{-4}/\text{cm}$ in an energy range of 1.5 eV to 2.3 eV.

10 [0051]

A structure of an oxide semiconductor layer is described below.

[0052]

An oxide semiconductor layer is classified roughly into a single-crystal oxide semiconductor layer and a non-single-crystal oxide semiconductor layer. The non-single-crystal oxide semiconductor layer includes any of a c-axis aligned crystalline oxide semiconductor (CAAC-OS) layer, a polycrystalline oxide semiconductor layer, a microcrystalline oxide semiconductor layer, an amorphous oxide semiconductor layer, and the like.

[0053]

20 First, a CAAC-OS layer is described.

[0054]

The CAAC-OS layer is one of oxide semiconductor layers including a plurality of c-axis aligned crystal parts.

[0055]

25 In a transmission electron microscope (TEM) image of the CAAC-OS layer, a boundary between crystal parts, that is, a grain boundary is not clearly observed. Thus, in the CAAC-OS layer, a reduction in electron mobility due to the grain boundary is less likely to occur.

[0056]

According to the TEM image of the CAAC-OS layer observed in a direction substantially parallel to a sample surface (cross-sectional TEM image), metal atoms are arranged in a layered manner in the crystal parts. Each metal atom layer has a morphology reflected by a surface where the CAAC-OS layer is formed (hereinafter, a surface where the CAAC-OS layer is formed is referred to as a formation surface) or a top surface of the CAAC-OS layer, and is arranged in parallel to the formation surface or the top surface of the CAAC-OS layer.

[0057]

In this specification, a term "parallel" indicates that the angle formed between two straight lines is greater than or equal to -10° and less than or equal to 10° , and accordingly also includes the case where the angle is greater than or equal to -5° and less than or equal to 5° . In addition, a term "perpendicular" indicates that the angle formed between two straight lines is greater than or equal to 80° and less than or equal to 100° , and accordingly includes the case where the angle is greater than or equal to 85° and less than or equal to 95° .

[0058]

In this specification, the trigonal and rhombohedral crystal systems are included in the hexagonal crystal system.

[0059]

On the other hand, according to the TEM image of the CAAC-OS layer observed in a direction substantially perpendicular to the sample surface (plan TEM image), metal atoms are arranged in a triangular or hexagonal configuration in the crystal parts. However, there is no regularity of arrangement of metal atoms between different crystal parts.

[0060]

From the results of the cross-sectional TEM image and the plan TEM image, alignment is found in the crystal parts in the CAAC-OS layer.

[0061]

Most of the crystal parts included in the CAAC-OS layer each fit inside a cube whose one side is less than 100 nm. Thus, there is a case where a crystal part included in the CAAC-OS layer fits inside a cube whose one side is less than 10 nm, less than 5

nm, or less than 3 nm. Note that when a plurality of crystal parts included in the CAAC-OS layer are connected to each other, one large crystal region is formed in some cases. For example, a crystal region with an area of 2500 nm^2 or more, $5 \text{ }\mu\text{m}^2$ or more, or $1000 \text{ }\mu\text{m}^2$ or more is observed in some cases in the plan TEM image.

5 [0062]

A CAAC-OS layer is subjected to structural analysis with an X-ray diffraction (XRD) apparatus. For example, when the CAAC-OS layer including an InGaZnO_4 crystal is analyzed by an out-of-plane method, a peak appears frequently when the diffraction angle (2θ) is around 31° . This peak is derived from the (009) plane of the
10 InGaZnO_4 crystal, which indicates that crystals in the CAAC-OS layer have c-axis alignment, and that the c-axes are aligned in a direction substantially perpendicular to the formation surface or the top surface of the CAAC-OS layer.

[0063]

On the other hand, when the CAAC-OS layer is analyzed by an in-plane
15 method in which an X-ray enters a sample in a direction substantially perpendicular to the c-axis, a peak appears frequently when 2θ is around 56° . This peak is derived from the (110) plane of the InGaZnO_4 crystal. Here, analysis (ϕ scan) is performed under conditions where the sample is rotated around a normal vector of a sample surface as an axis (ϕ axis) with 2θ fixed at around 56° . In the case where the sample is a
20 single-crystal oxide semiconductor layer of InGaZnO_4 , six peaks appear. The six peaks are derived from crystal planes equivalent to the (110) plane. On the other hand, in the case of a CAAC-OS layer, a peak is not clearly observed even when ϕ scan is performed with 2θ fixed at around 56° .

[0064]

25 According to the above results, in the CAAC-OS layer having c-axis alignment, while the directions of a-axes and b-axes are different between crystal parts, the c-axes are aligned in a direction parallel to a normal vector of a formation surface or a normal vector of a top surface. Thus, each metal atom layer arranged in a layered manner observed in the cross-sectional TEM image corresponds to a plane parallel to the a-b
30 plane of the crystal.

[0065]

Note that the crystal part is formed concurrently with deposition of the CAAC-OS layer or is formed through crystallization treatment such as heat treatment. As described above, the c-axis of the crystal is aligned in a direction parallel to a normal vector of a formation surface or a normal vector of a top surface. Thus, for example, in the case where a shape of the CAAC-OS layer is changed by etching or the like, the c-axis might not be necessarily parallel to a normal vector of a formation surface or a normal vector of a top surface of the CAAC-OS layer.

[0066]

In the CAAC-OS layer, distribution of c-axis aligned crystal parts is not necessarily uniform. For example, in the case where crystal growth leading to the crystal parts of the CAAC-OS layer occurs from the vicinity of the top surface of the layer, the proportion of the c-axis aligned crystal parts in the vicinity of the top surface is higher than that in the vicinity of the formation surface in some cases. Further, when an impurity is added to the CAAC-OS layer, a region to which the impurity is added is altered, and the proportion of the c-axis aligned crystal parts in the CAAC-OS layer varies depending on regions, in some cases.

[0067]

Note that when the CAAC-OS layer with an InGaZnO_4 crystal is analyzed by an out-of-plane method, a peak of 2θ may also be observed at around 36° , in addition to the peak of 2θ at around 31° . The peak of 2θ at around 36° indicates that a crystal having no c-axis alignment is included in part of the CAAC-OS layer. It is preferable that in the CAAC-OS layer, a peak of 2θ appear at around 31° and a peak of 2θ do not appear at around 36° .

[0068]

The CAAC-OS layer is an oxide semiconductor layer having a low impurity concentration. The impurity means an element other than main components of the oxide semiconductor layer, such as hydrogen, carbon, silicon, or a transition metal element. In particular, an element (e.g., silicon) having higher strength of bonding to oxygen than a metal element included in the oxide semiconductor layer takes oxygen away in the oxide semiconductor layer to disrupt the atomic arrangement in the oxide semiconductor layer, which causes a lowering of the crystallinity of the oxide

semiconductor layer. A heavy metal such as iron or nickel, argon, carbon dioxide, or the like has a large atomic radius (or molecular radius), and thus disrupts the atomic arrangement in the oxide semiconductor layer when included in the oxide semiconductor layer, which causes a lowering of the crystallinity of the oxide semiconductor layer. Note that the impurity included in the oxide semiconductor layer serves as a carrier trap or a carrier generation source in some cases.

[0069]

The CAAC-OS layer is an oxide semiconductor layer having a low density of defect states. For example, oxygen vacancies in the oxide semiconductor layer serve as carrier traps or serve as carrier generation sources when hydrogen is captured therein.

[0070]

The state in which impurity concentration is low and density of defect states is low (few oxygen vacancies) is referred to as "highly purified intrinsic" or "substantially highly purified intrinsic". A highly purified intrinsic or substantially highly purified intrinsic oxide semiconductor layer has few carrier generation sources, and thus has a low carrier density. Thus, a transistor including the oxide semiconductor layer rarely has a negative threshold voltage (rarely has normally-on characteristics). A highly purified intrinsic or substantially highly purified intrinsic oxide semiconductor layer has few carrier traps. Thus, the transistor including the oxide semiconductor layer has a small variation in electric characteristics and accordingly has high reliability. Charges trapped by the carrier traps in the oxide semiconductor layer take a long time to be released and may behave like fixed charges. Thus, the transistor including the oxide semiconductor layer with a high impurity concentration and a high density of defect states has unstable electric characteristics in some cases.

[0071]

In a transistor using the CAAC-OS layer, change in electric characteristics due to irradiation with visible light or ultraviolet light is small.

[0072]

Next, a microcrystalline oxide semiconductor layer is described.

[0073]

In an image obtained with a TEM, crystal parts cannot be found clearly in the microcrystalline oxide semiconductor layer in some cases. In most cases, the size of a

crystal part included in the microcrystalline oxide semiconductor layer is greater than or equal to 1 nm and less than or equal to 100 nm, or greater than or equal to 1 nm and less than or equal to 10 nm. A microcrystal with a size greater than or equal to 1 nm and less than or equal to 10 nm, or a size greater than or equal to 1 nm and less than or equal to 3 nm is specifically referred to as nanocrystal (nc). An oxide semiconductor layer including nanocrystal is referred to as an nc-OS (nanocrystalline oxide semiconductor) layer. In an image of the nc-OS layer obtained with a TEM, for example, a boundary between crystal parts is not clearly detected in some cases.

[0074]

In the nc-OS layer, a microscopic region (for example, a region with a size greater than or equal to 1 nm and less than or equal to 10 nm, in particular, a region with a size greater than or equal to 1 nm and less than or equal to 3 nm) has a periodic atomic order. However, there is no regularity of crystal orientation between different crystal parts in the nc-OS layer; thus, the orientation of the whole layer is not observed. Accordingly, in some cases, the nc-OS layer cannot be distinguished from an amorphous oxide semiconductor depending on an analysis method. For example, when the nc-OS layer is subjected to structural analysis by an out-of-plane method with an XRD apparatus using an X-ray having a diameter larger than that of a crystal part, a peak which shows a crystal plane does not appear. Further, a halo pattern is shown in a selected-area electron diffraction pattern of the nc-OS layer obtained by using an electron beam having a diameter (e.g., larger than or equal to 50 nm) larger than that of a crystal part. Meanwhile, spots are shown in a nanobeam electron diffraction pattern of the nc-OS layer obtained by using an electron beam having a diameter (e.g., larger than or equal to 1 nm and smaller than or equal to 30 nm) close to, or smaller than or equal to that of a crystal part. Further, in a nanobeam electron diffraction pattern of the nc-OS layer, regions with high luminance in a circular (ring) pattern are shown in some cases. Also in a nanobeam electron diffraction pattern of the nc-OS layer, a plurality of spots is shown in a ring-like region in some cases.

[0075]

Since the nc-OS layer is an oxide semiconductor layer having more regularity than the amorphous oxide semiconductor layer, the nc-OS layer has a lower density of defect states than the amorphous oxide semiconductor layer. However, there is no

regularity of crystal orientation between different crystal parts in the nc-OS layer; hence, the nc-OS layer has a higher density of defect states than the CAAC-OS layer.

[0076]

Each of the oxide semiconductor layers 101a to 101c is formed using, for example, any of an amorphous oxide semiconductor layer, a microcrystalline oxide semiconductor layer, and a CAAC-OS layer.

[0077]

Oxide semiconductors having different crystallinities may be used for the oxide semiconductor layers 101a to 101c. That is, the oxide semiconductor layers 101a to 101c may be formed using any of a microcrystalline oxide semiconductor, an amorphous oxide semiconductor, and a CAAC-OS, as appropriate. By using a CAAC-OS for the oxide semiconductor layer 101b, oxygen vacancies in the film can be further reduced, which is preferable.

[0078]

In an amorphous oxide semiconductor, impurities are easily captured and accordingly, the carrier density tends to increase; thus, relatively high field-effect mobility can be obtained with relative ease.

[0079]

The crystallinity of an oxide semiconductor layer can be increased by deposition of the oxide semiconductor layer on a flat surface. For example, the oxide semiconductor layer is favorably formed on a surface with an average surface roughness (R_a) of 1 nm or less, preferably 0.3 nm or less, more preferably 0.1 nm or less.

[0080]

Note that R_a is obtained by expanding arithmetic mean surface roughness, which is defined by JIS B 0601:2001 (ISO4287:1997), into three dimensions so as to be applied to a curved surface, and is an average value of the absolute values of deviations from a reference surface to a specific surface. Here, R_a can be expressed as an "average value of the absolute values of deviations from a reference surface to a specific surface" and is defined by the following formula.

[0081]

[FORMULA 2]

$$Ra = \frac{1}{S_0} \int_{y_1}^{y_2} \int_{x_1}^{x_2} |f(x, y) - Z_0| dx dy$$

[0082]

Here, the specific surface is a surface that is a target of roughness measurement, and is a quadrilateral region specified by four points represented by the coordinates (x_1 , y_1 , $f(x_1, y_1)$), (x_1 , y_2 , $f(x_1, y_2)$), (x_2 , y_1 , $f(x_2, y_1)$), and (x_2 , y_2 , $f(x_2, y_2)$). Further, S_0 represents the area of a rectangle obtained by projecting the specific surface on the xy plane, and Z_0 represents the height of the reference surface (the average height of the specific surface). Note that R_a can be measured using an atomic force microscope (AFM).

10 [0083]

The thickness of each of the first oxide semiconductor layer 101a, the second oxide semiconductor layer 101b, and the third oxide semiconductor layer 101c is preferably greater than or equal to 1 nm and less than or equal to 50 nm, more preferably greater than or equal to 5 nm and less than or equal to 20 nm.

15 [0084]

The structures, methods, and the like described in this embodiment can be combined as appropriate with any of the other structures, methods, and the like described in the other embodiments.

[0085]

20 (Embodiment 2)

In this embodiment, embodiments of semiconductor devices of one embodiment of the present invention are described with reference to FIGS. 4A to 4C, FIGS. 5A and 5B, FIGS. 6A and 6B, and FIGS. 7A and 7B.

[0086]

25 There is no particular limitation on the structure of the transistor included in a semiconductor device of one embodiment of the present invention; for example, a staggered type or a planar type having a top-gate structure or a bottom-gate structure can be employed. Further, the transistor may have a single-gate structure including one channel formation region, or a multi-gate structure such as a double-gate structure

including two channel formation regions or a triple-gate structure including three channel formation regions. Alternatively, the transistor may have a dual-gate structure including two gate electrode layers positioned above and below a channel formation region with a gate insulating film provided therebetween.

5 [0087]

FIGS. 4A to 4C illustrate a structural example of a bottom-gate transistor 310. FIG. 4A is a plan view of the transistor 310, FIG. 4B is a cross-sectional view taken along a dashed-dotted line A1-A2 in FIG. 4A, and FIG. 4C is a cross-sectional view taken along a dashed-dotted line B1-B2 in FIG. 4A.

10 [0088]

The transistor 310 includes a gate electrode layer 401 provided over a substrate 400 having an insulating surface, a gate insulating film 402 provided over the gate electrode layer 401, an oxide semiconductor stacked film 404 overlapping with the gate electrode layer 401 with the gate insulating film 402 interposed therebetween, and a source electrode layer 405a and a drain electrode layer 405b which are provided in contact with the oxide semiconductor stacked film 404. Further, an insulating film 406 is provided to cover the source electrode layer 405a and the drain electrode layer 405b and to be in contact with the oxide semiconductor stacked film 404.

[0089]

20 As the oxide semiconductor stacked film 404, the oxide semiconductor stacked film illustrated in Embodiment 1, in which a plurality of oxide semiconductor layers is stacked, can be used. The oxide semiconductor stacked film 404 includes, for example, indium, gallium, and zinc, and has a structure in which a first oxide semiconductor layer 404a, a second oxide semiconductor layer 404b, and a third oxide semiconductor layer 404c are sequentially stacked. Note that in this embodiment, the oxide semiconductor stacked film has a three-layer structure as illustrated in FIG. 1A; however, like in the oxide semiconductor stacked film illustrated in FIG. 1B, the second semiconductor layer may further have a stacked-layer structure.

25 [0090]

30 In the oxide semiconductor stacked film 404, the content percentage of indium in the oxide semiconductor layer 404b is preferably higher than that in the oxide semiconductor layer 404a and is preferably higher than that in the oxide semiconductor

layer 404c.

[0091]

Furthermore, in the oxide semiconductor layer 404b, the content percentage of indium is preferably higher than that of gallium.

5 [0092]

For example, it is preferable that the oxide semiconductor layer 404a have an atomic ratio of In:Ga:Zn = 1:3:2, the oxide semiconductor layer 404b have an atomic ratio of In:Ga:Zn = 1:1:1, and the oxide semiconductor layer 404c have an atomic ratio of In:Ga:Zn = 1:3:2. Note that a proportion of each atom in the atomic ratio of the oxide semiconductor layer varies within a range of $\pm 20\%$, or within a range of $\pm 10\%$ as an error.

[0093]

As the proportion of indium becomes higher in a metal oxide included in an oxide semiconductor, the conductivity of the metal oxide increases. For example, in the case where the content percentage of indium in the second oxide semiconductor layer 404b is higher than that in the first oxide semiconductor layer 404a and the third oxide semiconductor layer 404c, the conductivity σ_2 of the second oxide semiconductor layer 404b can be made higher than the conductivity σ_1 of the first oxide semiconductor layer 404a and the conductivity σ_3 of the third oxide semiconductor layer 404c.

20 [0094]

The conductivity σ_2 is higher than the conductivity σ_1 and the conductivity σ_3 by 1×10^3 S/cm or more, preferably by 1×10^5 S/cm or more.

[0095]

The oxide semiconductor stacked film 404 has the above stacked-layer structure, whereby the absorption coefficient due to the localized states measured by the CPM is lower than or equal to $3 \times 10^{-3}/\text{cm}$, preferably lower than or equal to $3 \times 10^{-4}/\text{cm}$.

[0096]

Each of the oxide semiconductor layers 404a to 404c is preferably formed using any of an amorphous oxide semiconductor, a single crystal oxide semiconductor, a polycrystalline oxide semiconductor, and a CAAC-OS. Further, oxide semiconductors

30

having different crystallinities may be used for the oxide semiconductor layers 404a to 404c. That is, the oxide semiconductor layers 404a to 404c may be formed using a combination of any of a single crystal oxide semiconductor, a polycrystalline oxide semiconductor, an amorphous oxide semiconductor, and a CAAC-OS as appropriate.

- 5 By using a CAAC-OS for the oxide semiconductor layer 404b, oxygen vacancies in the film can be further reduced, which is preferable.

[0097]

- In the case where the thickness of the first oxide semiconductor layer 404a which is provided on the gate electrode layer 401 side is too large, when voltage is applied to the gate electrode layer 401, carriers do not flow in an interface between the first oxide semiconductor layer 404a and the second oxide semiconductor layer 404b and flow through the first oxide semiconductor layer 404a. The thickness of each of the first oxide semiconductor layer 404a, the second oxide semiconductor layer 404b, and the third oxide semiconductor layer 404c is preferably greater than or equal to 1 nm and less than or equal to 50 nm, more preferably greater than or equal to 5 nm and less than or equal to 20 nm. For example, it is preferable that the thickness of the first oxide semiconductor layer 404a be greater than or equal to 5 nm and less than or equal to 15 nm, the thickness of the second oxide semiconductor layer 404b be greater than or equal to 15 nm and less than or equal to 35 nm, and the thickness of the third oxide semiconductor layer 404c be greater than or equal to 20 nm and less than or equal to 40 nm.

[0098]

- In the bottom-gate transistor 310, the conductivity of the oxide semiconductor layer 404b is made higher than that of the oxide semiconductor layer 404a and the oxide semiconductor layer 404c. With such a structure, even when voltage is applied to the gate electrode layer 401, carriers do not flow in an interface between the oxide semiconductor layer 404a and the gate insulating film 402 but flow in an interface between the oxide semiconductor layer 404b and the oxide semiconductor layer 404a. Further, the oxide semiconductor layer 404b and the oxide semiconductor layer 404a include the same constituent elements with different atomic ratios. Thus, oxygen vacancies at the interface between the oxide semiconductor layer 404b and the oxide semiconductor layer 404a are reduced. As a result, even if carriers flow in the

interface between the oxide semiconductor layer 404b and the oxide semiconductor layer 404a, the influence of the localized states due to the oxygen vacancies can be reduced. Accordingly, a variation in electrical characteristics of a transistor can be suppressed and a transistor with high reliability can be obtained.

5 [0099]

FIG. 5A illustrates a top-gate transistor 320.

[0100]

The transistor 320 includes an insulating film 408 provided over the substrate 400 having an insulating surface, the oxide semiconductor stacked film 404 provided
10 over the insulating film 408, the source electrode layer 405a and the drain electrode layer 405b which are provided in contact with the oxide semiconductor stacked film 404, a gate insulating film 409 provided over the oxide semiconductor stacked film 404, the source electrode layer 405a, and the drain electrode layer 405b, and a gate electrode layer 410 overlapping with the oxide semiconductor stacked film 404 with the gate
15 insulating film 409 interposed therebetween.

[0101]

In the oxide semiconductor stacked film 404 in the transistor 320 illustrated in FIG. 5A, the oxide semiconductor layer 404a, the oxide semiconductor layer 404b, and the oxide semiconductor layer 404c are stacked in this order.

20 [0102]

In the case where the thickness of the third oxide semiconductor layer 404c which is provided on the gate electrode layer 410 side is too large, when voltage is applied to the gate electrode layer 410, carriers do not flow in an interface between the third oxide semiconductor layer 404c and the second oxide semiconductor layer 404b
25 and flow through the third oxide semiconductor layer 404c. The thickness of each of the first oxide semiconductor layer 404a, the second oxide semiconductor layer 404b, and the third oxide semiconductor layer 404c is preferably greater than or equal to 1 nm and less than or equal to 50 nm, more preferably greater than or equal to 5 nm and less than or equal to 20 nm. For example, it is preferable that the thickness of the first
30 oxide semiconductor layer 404a be greater than or equal to 20 nm and less than or equal to 40 nm, the thickness of the second oxide semiconductor layer 404b be greater than or equal to 15 nm and less than or equal to 35 nm, and the thickness of the third oxide

semiconductor layer 404c be greater than or equal to 5 nm and less than or equal to 15 nm.

[0103]

Also in the top-gate transistor 320, the conductivity of the oxide semiconductor layer 404b is made higher than that of the oxide semiconductor layer 404a and an oxide semiconductor layer 404c. With such a structure, even when voltage is applied to the gate electrode layer 410, carriers do not flow in an interface between the oxide semiconductor layer 404c and the gate insulating film 409 but flow in an interface between the oxide semiconductor layer 404b and the oxide semiconductor layer 404c. Further, the oxide semiconductor layer 404b and the oxide semiconductor layer 404c include the same constituent elements with different atomic ratios. Thus, oxygen vacancies at the interface between the oxide semiconductor layer 404b and the oxide semiconductor layer 404c are reduced. As a result, even if carriers flow in the interface between the oxide semiconductor layer 404c and the oxide semiconductor layer 404b, the influence of the localized states due to the oxygen vacancies can be reduced. Accordingly, a variation in electrical characteristics of a transistor can be suppressed and a transistor with high reliability can be obtained.

[0104]

FIG. 5B illustrates a dual-gate transistor 330 including two gate electrode layers positioned above and below a channel formation region with a gate insulating film interposed therebetween.

[0105]

The transistor 330 includes the gate electrode layer 401 provided over the substrate 400 having an insulating surface, the gate insulating film 402 provided over the gate electrode layer 401, the oxide semiconductor stacked film 404 overlapping with the gate electrode layer 401 with the gate insulating film 402 interposed therebetween, the source electrode layer 405a and the drain electrode layer 405b which are provided in contact with the oxide semiconductor stacked film 404, the insulating film 406 which covers the source electrode layer 405a and the drain electrode layer 405b and is in contact with the oxide semiconductor stacked film 404, and an electrode layer 407 overlapping with the oxide semiconductor stacked film 404 with the insulating film 406 interposed therebetween.

[0106]

In the transistor 330, the insulating film 406 serves as a gate insulating film and the electrode layer 407 serves as a gate electrode layer. A signal for controlling an on state and an off state of the transistor is supplied to one of the pair of gate electrode
5 layers, and the other of the gate electrode layers may be electrically insulated to be in a floating state, or may be in a state where a potential is supplied from another element. In the latter case, potentials with the same level may be supplied to both of the gate electrode layers, or a fixed potential such as a ground potential may be supplied only to the other gate electrode layer. By controlling the level of potential supplied to the
10 other gate electrodes, the threshold voltage of the transistor 330 can be controlled.

[0107]

In the oxide semiconductor stacked film 404 in the transistor 330 illustrated in FIG. 5B, the oxide semiconductor layer 404a, the oxide semiconductor layer 404b, and the oxide semiconductor layer 404c are stacked in this order.

15 [0108]

Also in the dual-gate transistor 330, the conductivity of the oxide semiconductor layer 404b is made higher than that of the oxide semiconductor layer 404a and the oxide semiconductor layer 404c. With such a structure, even when voltage is applied to the gate electrode layer 410, carriers do not flow in an interface
20 between the oxide semiconductor layer 404c and the gate insulating film 409 but flow in an interface between the oxide semiconductor layer 404b and the oxide semiconductor layer 404c. Further, the oxide semiconductor layer 404b and the oxide semiconductor layer 404c include the same constituent elements with different atomic ratios. Thus, oxygen vacancies at the interface between the oxide semiconductor layer
25 404b and the oxide semiconductor layer 404c are reduced. As a result, even if carriers flow in the interface between the oxide semiconductor layer 404c and the oxide semiconductor layer 404b, the influence of the localized states due to the oxygen vacancies can be reduced. Accordingly, a variation in electrical characteristics of a transistor can be suppressed and a transistor with high reliability can be obtained.

30 [0109]

Here, the energy band structures of a single oxide semiconductor layer and stacked oxide semiconductor layers are described with reference to FIGS. 6A and 6B

and FIGS. 7A and 7B.

[0110]

FIG. 6A illustrates a cross-sectional view of a transistor using a single oxide semiconductor layer, and FIG. 6B shows (a schematic view of) an energy band diagram of a cross section along X1-X2 in FIG. 6A.

[0111]

The transistor illustrated in FIG. 6A includes an oxide semiconductor layer 411 provided over the substrate 400 with the insulating film 408 interposed therebetween, the source electrode layer 405a and the drain electrode layer 405b which are provided over the oxide semiconductor layer 411, the gate insulating film 409 provided to cover the oxide semiconductor layer 411, the source electrode layer 405a, and the drain electrode layer 405b, and the gate electrode layer 410 provided over the oxide semiconductor layer 411 with the gate insulating film 409 interposed therebetween.

[0112]

In FIG. 6A, the oxide semiconductor layer 411 is an In-Ga-Zn-based oxide (also referred to as IGZO) layer and the insulating film 408 and the gate insulating film 409 are each a silicon oxynitride film.

[0113]

FIG. 7A illustrates a cross-sectional view of a transistor using stacked oxide semiconductor layers (IGZO layers), and FIG. 7B shows (a schematic view of) an energy band diagram of a cross section along Y1-Y2 in FIG. 7A.

[0114]

The transistor illustrated in FIG. 7A includes the oxide semiconductor stacked film 404 provided over the substrate 400 with the insulating film 408 interposed therebetween, the source electrode layer 405a and the drain electrode layer 405b which are provided over the oxide semiconductor stacked film 404, the gate insulating film 409 provided to cover the oxide semiconductor stacked film 404, the source electrode layer 405a, and the drain electrode layer 405b, and the gate electrode layer 410 provided over the oxide semiconductor stacked film 404 with the gate insulating film 409 interposed therebetween.

[0115]

In the oxide semiconductor stacked film 404 illustrated in FIG. 7A, the oxide

semiconductor layers 404a and 404c are each an IGZO layer formed using a target having an atomic ratio of $\text{In:Ga:Zn} = 1:3:2$ and the oxide semiconductor layer 404b is an IGZO layer formed using a target having an atomic ratio of $\text{In:Ga:Zn} = 1:1:1$. In FIG. 7A, the insulating film 408 and the gate insulating film 409 are each a silicon oxynitride film.

[0116]

As illustrated in FIG. 6B, in the case where the oxide semiconductor layer is a single layer, silicon in the silicon oxynitride film over or under the IGZO layer is mixed into the IGZO layer at about several nanometers from the interfaces in some cases. When the silicon enters the IGZO layer, impurity states are formed. The impurity states serve as donors to generate electrons; thus, an n-type semiconductor is formed. Accordingly, the band of the oxide semiconductor is bended as illustrated in FIG. 6B. Further, when the silicon is mixed into the IGZO layer, the IGZO layer easily becomes amorphous. Further, there are interface scattering or scattering of impurities such as Si; thus, a reduction in electron mobility is concerned.

[0117]

On the other hand, in the case where the oxide semiconductor layer has a three-layer structure as illustrated in FIG. 7B, even when silicon is mixed into the oxide semiconductor stacked film 404, the silicon is mixed into only the first oxide semiconductor layer 404a and the third oxide semiconductor layer 404c and is not easily mixed into the second oxide semiconductor layer 404b. The electron affinity of the first oxide semiconductor layer 404a and the third oxide semiconductor layer 404c each using the IGZO layer having an atomic ratio of $\text{In:Ga:Zn} = 1:3:2$ is smaller than that of the second oxide semiconductor layer 404b using the IGZO layer having an atomic ratio of $\text{In:Ga:Zn} = 1:1:1$. Thus, the conduction band of the oxide semiconductor stacked film 404 has a well structure as illustrated in FIG. 7B.

[0118]

Silicon is mixed into the oxide semiconductor stacked film 404 in some cases; however, when the thicknesses of the first oxide semiconductor layer 404a and the third oxide semiconductor layer 404c are larger than several nanometers, silicon does not reach the second oxide semiconductor layer 404b; thus, the influence of mixing silicon

is reduced.

[0119]

In the transistor including the oxide semiconductor stacked film 404, the electron affinity of the second oxide semiconductor layer 404b is larger than that of the layers over and under the second oxide semiconductor layer 404b; thus, the second oxide semiconductor layer 404b mainly serves as an electron path. Further, since electrons flow through the second oxide semiconductor layer 404b, a trap due to the impurity states of the first oxide semiconductor layer 404a and the third oxide semiconductor layer 404c is not easily generated.

[0120]

No or little silicon is mixed into the second oxide semiconductor layer 404b; thus, at least a region in the second oxide semiconductor layer 404b, where a channel is formed, can be made a CAAC-OS layer. Further, there are hardly interface scattering or scattering of impurities such as silicon; thus, electron mobility is improved.

[0121]

The structures, methods, and the like described in this embodiment can be combined as appropriate with any of the other structures, methods, and the like described in the other embodiments.

[0122]

(Embodiment 3)

In this embodiment, a method for manufacturing the transistor using the oxide semiconductor stacked film illustrated in FIGS. 4A to 4C is described with reference to FIGS. 8A to 8E.

[0123]

First, the gate electrode layer 401 is formed over the substrate 400 (see FIG. 8A).

[0124]

There is no particular limitation on a substrate that can be used as the substrate 400 having an insulating surface as long as it has heat resistance enough to withstand heat treatment performed later. A variety of glass substrates for electronics industry, such as a barium borosilicate glass substrate and an aluminoborosilicate glass substrate, can be used as the substrate 400. Note that as the substrate, a substrate having a

thermal expansion coefficient of greater than or equal to $25 \times 10^{-7}/^{\circ}\text{C}$ and less than or equal to $50 \times 10^{-7}/^{\circ}\text{C}$ (preferably greater than or equal to $30 \times 10^{-7}/^{\circ}\text{C}$ and less than or equal to $40 \times 10^{-7}/^{\circ}\text{C}$) and a strain point of higher than or equal to 650°C and lower than or equal to 750°C (preferably higher than or equal to 700°C and lower than or equal to 740°C) is preferably used.

[0125]

In the case where a large-sized glass substrate with any of the 5th generation (1000 mm $\times$ 1200 mm or 1300 mm $\times$ 1700 mm), the 6th generation (1700 mm $\times$ 1800 mm), the 7th generation (1870 mm $\times$ 2200 mm), the 8th generation (2200 mm $\times$ 2700 mm), the 9th generation (2400 mm $\times$ 2800 mm), and the 10th generation (2880 mm $\times$ 3130 mm) is used, minute processing might become difficult owing to shrinkage of the substrate caused by heat treatment or the like in the process for manufacturing a semiconductor device. Therefore, when such a large-sized glass substrate is used as the substrate, the one with a small shrinkage is preferably used. For example, as the substrate, a large-sized glass substrate whose shrinkage by heat treatment for one hour at preferably 450°C , more preferably 700°C is less than or equal to 20 ppm, preferably less than or equal to 10 ppm, more preferably less than or equal to 5 ppm may be used.

[0126]

Alternatively, a ceramic substrate, a quartz substrate, a sapphire substrate, or the like can be used as the substrate 400. Alternatively, a single crystal semiconductor substrate or a polycrystalline semiconductor substrate made of silicon or silicon carbide, a compound semiconductor substrate made of silicon germanium or the like, an SOI substrate, or the like can be used. Alternatively, any of these substrates over which a semiconductor element is provided may be used.

[0127]

The semiconductor device may be manufactured using a flexible substrate as the substrate 400. To manufacture a flexible semiconductor device, the transistor 310 including the oxide semiconductor stacked film 404 may be directly formed over a flexible substrate; or alternatively, the transistor 310 including the oxide semiconductor stacked film 404 may be formed over a manufacturing substrate, and then the transistor may be separated from the manufacturing substrate and transferred to a flexible

substrate. Note that, in order to separate the transistor from the manufacturing substrate and transfer it to the flexible substrate, a separation layer may be provided between the manufacturing substrate and the transistor 310 including the oxide semiconductor stacked film.

5 [0128]

The gate electrode layer 401 can be formed with the use of a metal material such as molybdenum, titanium, tantalum, tungsten, aluminum, copper, chromium, neodymium, or scandium or an alloy material which contains any of these materials as its main component. A semiconductor film which is doped with an impurity element
10 such as phosphorus and is typified by a polycrystalline silicon film, or a silicide film of nickel silicide or the like can also be used as the gate electrode layer 401. The gate electrode layer 401 has either a single-layer structure or a stacked-layer structure.

[0129]

The gate electrode layer 401 can also be formed using a conductive material
15 such as indium oxide-tin oxide, indium oxide containing tungsten oxide, indium zinc oxide containing tungsten oxide, indium oxide containing titanium oxide, indium tin oxide containing titanium oxide, indium oxide-zinc oxide, or indium tin oxide to which silicon oxide is added. The gate electrode layer 401 can have a stacked structure of the above conductive material and the above metal material.

20 [0130]

As the gate electrode layer 401, a metal oxide film containing nitrogen, specifically, an In-Ga-Zn-O film containing nitrogen, an In-Sn-O film containing nitrogen, an In-Ga-O film containing nitrogen, an In-Zn-O film containing nitrogen, a Sn-O film containing nitrogen, an In-O film containing nitrogen, or a metal nitride (e.g.,
25 InN or SnN) film can be used.

[0131]

The gate insulating film 402 can be formed by a sputtering method or a CVD method using a deposition gas. As the CVD method, an LPCVD method, a plasma CVD method, or the like can be used, and as another method, a coating film or the like
30 can also be used.

[0132]

The gate insulating film 402 can be formed using a silicon oxide film, a

gallium oxide film, an aluminum oxide film, a silicon nitride film, a silicon oxynitride film, an aluminum oxynitride film, or a silicon nitride oxide film.

[0133]

When the gate insulating film 402 is formed using a high-k material such as hafnium oxide, yttrium oxide, hafnium silicate (HfSi_xO_y ($x > 0, y > 0$)), hafnium silicate to which nitrogen is added (HfSiO_xN_y ($x > 0, y > 0$)), hafnium aluminate (HfAl_xO_y ($x > 0, y > 0$)), or lanthanum oxide, gate leakage current can be reduced. Further, the gate insulating film 402 has either a single-layer structure or a stacked-layer structure.

[0134]

Note that a region which is included in the gate insulating film 402 and is in contact with a first oxide semiconductor layer 403a formed later (in this embodiment, the region is the gate insulating film) is preferably an oxide insulating film and preferably includes a region containing oxygen in excess of the stoichiometric composition (i.e., oxygen-excess region). In order to provide the oxygen-excess region in the gate insulating film 402, for example, the gate insulating film 402 may be formed in an oxygen atmosphere. Alternatively, oxygen may be introduced into the formed gate insulating film 402 to provide the oxygen-excess region. As a method for introducing oxygen, an ion implantation method, an ion doping method, a plasma immersion ion implantation method, plasma treatment, or the like may be employed.

[0135]

By providing the oxygen-excess region in the gate insulating film 402, oxygen can be supplied by performing heat treatment after the formation of the oxide semiconductor stacked film. Thus, oxygen vacancies contained in the oxide semiconductor stacked film can be reduced.

[0136]

In this embodiment, as the gate insulating film 402, a silicon nitride film and a silicon oxide film are formed.

[0137]

Next, the first oxide semiconductor layer 403a, a second oxide semiconductor layer 403b, and a third oxide semiconductor layer 403c to be included in the oxide semiconductor stacked film are sequentially formed over the gate insulating film 402 (see FIG. 8B).

[0138]

As the first oxide semiconductor layer 403a, the second oxide semiconductor layer 403b, and the third oxide semiconductor layer 403c to be included in the oxide semiconductor stacked film, any of the following can be used, for example: an In-Ga-Zn-based oxide, an In-Al-Zn-based oxide, an In-Sn-Zn-based oxide, an In-Hf-Zn-based oxide, an In-La-Zn-based oxide, an In-Ce-Zn-based oxide, an In-Pr-Zn-based oxide, an In-Nd-Zn-based oxide, an In-Sm-Zn-based oxide, an In-Eu-Zn-based oxide, an In-Gd-Zn-based oxide, an In-Tb-Zn-based oxide, an In-Dy-Zn-based oxide, an In-Ho-Zn-based oxide, an In-Er-Zn-based oxide, an In-Tm-Zn-based oxide, an In-Yb-Zn-based oxide, an In-Lu-Zn-based oxide, an In-Sn-Ga-Zn-based oxide, an In-Hf-Ga-Zn-based oxide, an In-Al-Ga-Zn-based oxide, an In-Sn-Al-Zn-based oxide, an In-Sn-Hf-Zn-based oxide, and an In-Hf-Al-Zn-based oxide.

[0139]

Note that here, for example, an "In-Ga-Zn-based oxide" means an oxide containing In, Ga, and Zn as its main components and there is no limitation on the ratio of In:Ga:Zn. The In-Ga-Zn-based oxide may contain a metal element other than the In, Ga, and Zn.

[0140]

Alternatively, a material represented by $\text{InMO}_3(\text{ZnO})_m$ ($m > 0$ is satisfied, and m is not an integer) may be used as an oxide semiconductor. Note that M represents one or more metal elements selected from Ga, Fe, Mn, and Co. Alternatively, as the oxide semiconductor, a material expressed by $\text{In}_2\text{SnO}_5(\text{ZnO})_n$ ($n > 0$, n is a natural number) may be used.

[0141]

For example, an In-Ga-Zn-based oxide having an atomic ratio of In: Ga: Zn = 1: 1: 1 (= 1/3: 1/3: 1/3), In: Ga: Zn = 2: 2: 1 (= 2/5: 2/5: 1/5), In: Ga: Zn = 3: 1: 2 (= 1/2: 1/6: 1/3), In: Ga: Zn = 1: 3: 2 (= 1/6: 1/2: 1/3), or an oxide having an atomic ratio close to the above atomic ratios can be used. Alternatively, an In-Sn-Zn-based oxide having an atomic ratio of In:Sn:Zn = 1:1:1 (= 1/3:1/3:1/3), In:Sn:Zn = 2:1:3 (= 1/3:1/6:1/2), or In:Sn:Zn = 2:1:5 (= 1/4:1/8:5/8), or an oxide having an atomic ratio close to the above

atomic ratios may be used.

[0142]

However, an oxide semiconductor containing indium is not limited to the materials given above; a material with an appropriate composition may be used depending on required electrical characteristics of the transistor (e.g., field-effect mobility, threshold voltage, and variation). In order to obtain the required electrical characteristics of the transistor, it is preferable that the carrier concentration, the impurity concentration, the defect density, the atomic ratio between a metal element and oxygen, the interatomic distance, the density, and the like be set to appropriate values.

[0143]

In this embodiment, the case where an IGZO layer having an atomic ratio of In:Ga:Zn = 1:3:2 is used as the first oxide semiconductor layer 403a, an IGZO layer having an atomic ratio of In:Ga:Zn = 1:1:1 is used as the second oxide semiconductor layer 403b, and an IGZO layer having an atomic ratio of In:Ga:Zn = 1:3:2 is used as the third oxide semiconductor layer 403c is described.

[0144]

The second oxide semiconductor layer 403b in the transistor 310 is formed of, for example, an oxide semiconductor layer including a crystal part. However, the formed second oxide semiconductor layer 403b does not necessarily include a crystal part, and in this case, the second oxide semiconductor layer 403b including a crystal part may be obtained by performing heat treatment on the amorphous oxide semiconductor in any of the steps after the formation of the second oxide semiconductor layer 403b. The heat treatment for crystallizing the amorphous oxide semiconductor is performed at a temperature higher than or equal to 250 °C and lower than or equal to 700 °C, preferably higher than or equal to 400 °C, more preferably higher than or equal to 550 °C. The heat treatment can also serve as another heat treatment in the manufacturing process. A laser irradiation apparatus may be used for the heat treatment for crystallization.

[0145]

The oxide semiconductor layers each can be formed by a sputtering method, a molecular beam epitaxy (MBE) method, a CVD method, a pulse laser deposition

method, an atomic layer deposition (ALD) method, or the like as appropriate.

[0146]

In the formation of the oxide semiconductor layers 403a to 403c, the concentration of hydrogen to be contained is preferably reduced as much as possible.

- 5 In order to reduce the hydrogen concentration, for example, in the case where a sputtering method is used for the deposition, a high-purity rare gas (typically, argon) from which impurities such as hydrogen, water, a hydroxyl group, or a hydride have been removed; oxygen; or a mixed gas of oxygen and the rare gas is used as appropriate as an atmosphere gas supplied to a treatment chamber of a sputtering apparatus.

10 [0147]

The oxide semiconductor layer is formed in such a manner that a sputtering gas from which hydrogen and moisture are removed is introduced into a treatment chamber while moisture remaining in the treatment chamber is removed, whereby the concentration of hydrogen in the deposited oxide semiconductor layer can be reduced.

- 15 In order to remove the residual moisture in the treatment chamber, an entrapment vacuum pump, for example, a cryopump, an ion pump, or a titanium sublimation pump is preferably used. The evacuation unit may be a turbo molecular pump provided with a cold trap. A cryopump has a high capability in removing a hydrogen molecule, a compound containing a hydrogen atom such as water (H_2O) (preferably, also a
20 compound containing a carbon atom), and the like; thus, the impurity concentration in the oxide semiconductor film formed in the treatment chamber which is evacuated with the cryopump can be reduced.

[0148]

- Further, in the case where the oxide semiconductor layers 403a to 403c are
25 formed by a sputtering method, the relative density (the fill rate) of a metal oxide target which is used for forming the oxide semiconductor films is greater than or equal to 90 % and less than or equal to 100 %, preferably greater than or equal to 95 % and less than or equal to 99.9 %. With the use of the metal oxide target having high relative density, a dense oxide film can be formed.

30 [0149]

Note that formation of the oxide semiconductor layer while the substrate 400 is

kept at high temperatures is also effective in reducing the impurity concentration in the oxide semiconductor layer. The heating temperature of the substrate 400 may be higher than or equal to 150 °C and lower than or equal to 450 °C; the substrate temperature is preferably higher than or equal to 200 °C and lower than or equal to 350 °C. An oxide semiconductor layer is formed while the substrate is heated at a high temperature, whereby the oxide semiconductor film can have a crystalline portion.

[0150]

The conditions described below are preferably employed for the formation of the CAAC-OS layer.

10 [0151]

By reducing the amount of impurities entering the CAAC-OS layer during the deposition, the crystal state of the oxide semiconductor layer can be prevented from being broken by the impurities. For example, the concentration of impurities (e.g., hydrogen, water, carbon dioxide, or nitrogen) which exist in the treatment chamber may be reduced. Furthermore, the concentration of impurities in a deposition gas may be reduced. Specifically, a deposition gas whose dew point is −80 °C or lower, preferably −100 °C or lower is used.

[0152]

By increasing the substrate heating temperature during the deposition, migration of a sputtered particle is likely to occur after the sputtered particle is attached to a substrate surface. Specifically, the substrate heating temperature during the deposition is higher than or equal to 100 °C and lower than or equal to 740 °C, preferably higher than or equal to 200 °C and lower than or equal to 700 °C. By increasing the substrate heating temperature during the deposition, when the flat-plate-like sputtered particle reaches the substrate, migration occurs on the substrate surface, so that a flat plane of the flat-plate-like sputtered particle is attached to the substrate.

[0153]

Furthermore, it is preferable that the proportion of oxygen in the deposition gas be increased and the power be optimized in order to reduce plasma damage at the deposition. The proportion of oxygen in the deposition gas is 30 vol% or higher,

preferably 100 vol%.

[0154]

Note that the oxide semiconductor layers 403a to 403c are preferably formed in succession without exposure to the air. By forming the oxide semiconductor layers in succession without exposure to the air, attachment of hydrogen or a hydrogen compound (e.g., adsorption water) onto surfaces of the oxide semiconductor layers can be prevented. Thus, the entry of impurities can be prevented. In a similar manner, the gate insulating film 402 and the oxide semiconductor layer 403a are preferably formed in succession without exposure to the air.

[0155]

Further, heat treatment is preferably performed on the oxide semiconductor layers 403a to 403c in order to remove excess hydrogen (including water and a hydroxyl group) (to perform dehydration or dehydrogenation). The temperature of the heat treatment is higher than or equal to 300 °C and lower than or equal to 700 °C, or lower than the strain point of the substrate. The heat treatment can be performed under reduced pressure, a nitrogen atmosphere, or the like. Hydrogen, which is an impurity imparting n-type conductivity, can be removed by the heat treatment.

[0156]

Note that the heat treatment for the dehydration or dehydrogenation may be performed at any timing in the manufacturing process of the transistor as long as it is performed after the formation of the oxide semiconductor layer. For example, the heat treatment may be performed after the oxide semiconductor layer is processed into an island shape. The heat treatment for dehydration or dehydrogenation may be performed plural times, and may also serve as another heat treatment. A laser irradiation apparatus may be used for the heat treatment.

[0157]

In the heat treatment, it is preferable that water, hydrogen, or the like be not contained in nitrogen or a rare gas such as helium, neon, or argon. The purity of nitrogen or the rare gas such as helium, neon, or argon which is introduced into the heat treatment apparatus is set to preferably 6N (99.9999 %) or higher, further preferably 7N (99.99999 %) or higher (that is, the impurity concentration is preferably 1 ppm or lower,

further preferably 0.1 ppm or lower).

[0158]

In addition, after the oxide semiconductor layer is heated in the heat treatment, a high-purity oxygen gas, a high-purity dinitrogen monoxide gas, or ultra dry air (the moisture amount is less than or equal to 20 ppm (-55°C by conversion into a dew point), preferably less than or equal to 1 ppm, further preferably less than or equal to 10 ppb, in the measurement with use of a dew point meter of a cavity ring down laser spectroscopy (CRDS) system) may be introduced into the same furnace while the heating temperature is maintained or slow cooling is performed to lower the temperature from the heating temperature. It is preferable that water, hydrogen, or the like be not contained in the oxygen gas or the dinitrogen monoxide gas. The purity of the oxygen gas or the dinitrogen monoxide gas which is introduced into the heat treatment apparatus is preferably 6N or more, further preferably 7N or more (that is, the impurity concentration in the oxygen gas or the dinitrogen monoxide gas is preferably 1 ppm or lower, further preferably 0.1 ppm or lower). The oxygen gas or the dinitrogen monoxide gas acts to supply oxygen which is a main component of the oxide semiconductor and that has been reduced by the step of removing an impurity for the dehydration or dehydrogenation, so that the oxide semiconductor layer can have high purity and be an i-type (intrinsic) oxide semiconductor layer.

[0159]

Since there is a possibility that oxygen is also released and reduced by dehydration or dehydrogenation treatment, oxygen (including at least one of an oxygen radical, an oxygen atom, and an oxygen ion) may be introduced into the oxide semiconductor layers which have been subjected to the dehydration or dehydrogenation treatment to supply oxygen to the layers.

[0160]

Oxygen is added to the dehydrated or dehydrogenated oxide semiconductor layer to be supplied thereto, so that the oxide semiconductor layer can be highly purified and be i-type (intrinsic). Variations in electrical characteristics of a transistor having the highly-purified and i-type (intrinsic) oxide semiconductor are suppressed, and the transistor is electrically stable.

[0161]

In the step of introduction of oxygen, oxygen may be directly introduced to the oxide semiconductor stacked film (or the oxide semiconductor layer) or oxygen may be introduced to the oxide semiconductor stacked film through another insulating layer to be formed later. As a method for introducing oxygen (including at least one of an oxygen radical, an oxygen atom, and an oxygen ion), an ion implantation method, an ion doping method, a plasma immersion ion implantation method, plasma treatment, or the like can be used. A gas containing oxygen can be used for oxygen introduction treatment. As the gas containing oxygen, oxygen, dinitrogen monoxide, nitrogen dioxide, carbon dioxide, carbon monoxide, and the like can be used. Further, a rare gas may be contained in the gas containing oxygen in the oxygen introduction treatment.

[0162]

For example, in the case where an oxygen ion is implanted by an ion implantation method, the dose can be greater than or equal to 1×10^{13} ions/cm² and less than or equal to 5×10^{16} ions/cm².

[0163]

The timing of supply of oxygen to the oxide semiconductor stacked film is not particularly limited to the above as long as it is after the formation of the oxide semiconductor stacked film. The step of introducing oxygen may be performed plural times.

[0164]

Next, the oxide semiconductor layers 403a to 403c are processed by etching treatment using a photolithography method into the island-shaped first oxide semiconductor layer 404a, second oxide semiconductor layer 404b, and third oxide semiconductor layer 404c, respectively, whereby the oxide semiconductor stacked film 404 is formed (see FIG. 8C).

[0165]

Note that in this embodiment, the first oxide semiconductor layer 404a, the second oxide semiconductor layer 404b, and the third oxide semiconductor layer 404c are processed into island shapes by one etching treatment; thus, the ends of the oxide semiconductor layers included in the oxide semiconductor stacked film 404 are aligned

with each other. Note that in this specification, "aligning with" includes "substantially aligning with". For example, an end of a layer A and an end of a layer B, which are included in a stacked-layer structure etched using the same mask, are considered to be aligned with each other.

5 [0166]

Then, a conductive film is formed over the oxide semiconductor stacked film 404 and processed to form the source electrode layer 405a and the drain electrode layer 405b (including a wiring formed using the same layer) (see FIG. 8D).

[0167]

10 The source electrode layer 405a and the drain electrode layer 405b can be formed using, for example, a metal film containing an element selected from aluminum, chromium, copper, tantalum, titanium, molybdenum, and tungsten, a metal nitride film containing any of these elements as its component (a titanium nitride film, a molybdenum nitride film, or a tungsten nitride film), or the like. Alternatively, a film
15 of a high-melting-point metal such as titanium, molybdenum, or tungsten or a metal nitride film of any of these elements (a titanium nitride film, a molybdenum nitride film, or a tungsten nitride film) may be stacked on one of or both a bottom side and a top side of a metal film of aluminum, copper, or the like. Further alternatively, the conductive film used as the source electrode layer 405a and the drain electrode layer 405b may be
20 formed using a conductive metal oxide. As the conductive metal oxide, indium oxide (In_2O_3), tin oxide (SnO_2), zinc oxide (ZnO), indium oxide-tin oxide ($\text{In}_2\text{O}_3\text{-SnO}_2$), indium oxide-zinc oxide ($\text{In}_2\text{O}_3\text{-ZnO}$), or any of these metal oxide materials containing silicon oxide can be used.

[0168]

25 The insulating film 406 can be formed by a plasma CVD method, a sputtering method, an evaporation method, or the like.

[0169]

30 The insulating film 406 can be a single layer or a stacked layer of a silicon oxide film, a silicon oxynitride film, an aluminum oxide film, an aluminum oxynitride film, an inorganic insulating film such as a gallium oxide film, a hafnium oxide film, a magnesium oxide film, a zirconium oxide film, a lanthanum oxide film, a barium oxide film, a silicon nitride film, a silicon nitride oxide film, an aluminum nitride film, or an

aluminum nitride oxide film, or the like.

[0170]

In this embodiment, as the insulating film 406, a silicon oxide film is formed.

[0171]

5 Here, in order to form an oxygen-excess region in the insulating film 406, the step of adding oxygen to the insulating film 406 may be performed. The step of adding oxygen to the insulating film 406 can be performed in a manner similar to the step of adding oxygen to the gate insulating film 402.

[0172]

10 In addition, a planarization insulating film may be formed over the transistor in order that surface unevenness due to the transistor is reduced. As the planarization insulating film, an organic material such as a polyimide-, acrylic-, or benzocyclobutene-based resin can be used. Other than such organic materials, it is also possible to use a low-dielectric constant material (a low-k material) or the like.

15 Note that the planarization insulating film may be formed by stacking a plurality of insulating films formed from these materials.

[0173]

Through the above steps, a semiconductor device of the present invention can be manufactured (see FIG. 8E).

20 [0174]

An oxide insulating film is used as an insulating film in contact with the oxide semiconductor stacked film 404 or an oxygen-excess region is formed in an insulating film, whereby excess oxygen contained in the insulating film can be supplied to the oxide semiconductor stacked film by heat treatment or the like. Thus, oxygen
25 vacancies contained in the oxide semiconductor stacked film can be reduced.

[0175]

As illustrated in FIG. 8E, three oxide semiconductor layers are provided, and the conductivity of the oxide semiconductor layer 404b is higher than that of the oxide semiconductor layer 404a and the oxide semiconductor layer 404c. With the above
30 structure, even when voltage is applied from the insulating film 406 side, carriers do not flow in an interface between the oxide semiconductor layer 404c and the insulating film 406 but flow in an interface between the oxide semiconductor layer 404b and the oxide

semiconductor layer 404c. Further, the oxide semiconductor layer 404b and the oxide semiconductor layer 404c which have different atomic ratios are formed using the same element. Thus, oxygen vacancies at the interface between the oxide semiconductor layer 404b and the oxide semiconductor layer 404c are reduced. As a result, even if
5 carriers flow in the interface between the oxide semiconductor layer 404b and the oxide semiconductor layer 404c, the influence of the localized states due to the oxygen vacancies can be reduced.

[0176]

FIGS. 9A to 9D illustrate examples of oxide semiconductor stacked films in
10 bottom-gate transistors. These transistors have the same structure as the transistor 310 in FIGS. 4A to 4C except the oxide semiconductor stacked film.

[0177]

FIG. 9A illustrates a transistor 340 in which the second oxide semiconductor layer 404b and the third oxide semiconductor layer 404c are each processed into an
15 island shape and the first oxide semiconductor layer 403a is not processed in the oxide semiconductor stacked film.

[0178]

FIG. 9B illustrates a transistor 350 in which the first oxide semiconductor layer 404a and the second oxide semiconductor layer 404b are each processed into an island
20 shape and the third oxide semiconductor layer 403c is not processed in the oxide semiconductor stacked film.

[0179]

FIG. 9C illustrates a transistor 360 in which the second oxide semiconductor layer 404b is processed into an island shape and the first oxide semiconductor layer
25 403a and the third oxide semiconductor layer 403c are not processed in the oxide semiconductor stacked film.

[0180]

FIG. 9D illustrates a transistor 450 in which the first oxide semiconductor layer 404a and the second oxide semiconductor layer 404b are each processed into an island
30 shape and the third oxide semiconductor layer 404c is provided to cover the side surfaces of the first oxide semiconductor layer 404a and the second oxide semiconductor layer 404b in the oxide semiconductor stacked film.

[0181]

FIGS. 10A to 10D illustrate examples of oxide semiconductor stacked films in top-gate transistors. These transistors have the same structure as the transistor 320 in FIG. 5A except the oxide semiconductor stacked film.

5 [0182]

FIG. 10A illustrates a transistor 370 in which the second oxide semiconductor layer 404b and the third oxide semiconductor layer 404c are each processed into an island shape and the first oxide semiconductor layer 403a is not processed in the oxide semiconductor stacked film.

10 [0183]

FIG. 10B illustrates a transistor 380 in which the first oxide semiconductor layer 404a and the second oxide semiconductor layer 404b are each processed into an island shape and the third oxide semiconductor layer 403c is not processed in the oxide semiconductor stacked film.

15 [0184]

FIG. 10C illustrates a transistor 390 in which the second oxide semiconductor layer 404b is processed into an island shape and the first oxide semiconductor layer 403a and the third oxide semiconductor layer 403c are not processed in the oxide semiconductor stacked film.

20 [0185]

FIG. 10D illustrates a transistor 460 in which the first oxide semiconductor layer 404a and the second oxide semiconductor layer 404b are each processed into an island shape and the third oxide semiconductor layer 404c is provided to cover the side surfaces of the first oxide semiconductor layer 404a and the second oxide semiconductor layer 404b in the oxide semiconductor stacked film.

[0186]

As the proportion of indium becomes higher in a metal oxide included in an oxide semiconductor, the conductivity of the metal oxide increases. For example, in the case where the content percentage of indium in the second oxide semiconductor layer 404b is higher than those in the first oxide semiconductor layer 404a and the third oxide semiconductor layer 404c, the conductivity σ_2 of the second oxide semiconductor

30

layer 404b can be higher than the conductivity σ_1 of the first oxide semiconductor layer 404a and the conductivity σ_3 of the third oxide semiconductor layer 404c.

[0187]

The conductivity σ_2 is preferably higher than the conductivity σ_1 and the
5 conductivity σ_3 by 1×10^3 S/cm or more, more preferably by 1×10^5 S/cm or more.

[0188]

For example, the conductivity of the oxide semiconductor layer having an
atomic ratio of In:Ga:Zn = 1:1:1 is 6.5×10^{-5} S/cm to 4.5×10^{-1} S/cm. Further, the
conductivity of the oxide semiconductor layer having an atomic ratio of In:Ga:Zn =
10 3:1:2 is 2 S/cm to 9.7 S/cm. Further, the conductivity of the oxide semiconductor layer
having an atomic ratio of In:Ga:Zn = 1:3:2 is 1×10^{-7} S/cm (lower than the lower limit
of measurement).

[0189]

Therefore, even when the oxide semiconductor layer having an atomic ratio of
15 In:Ga:Zn = 1:3:2 is used as the first oxide semiconductor layer 403a or the third oxide
semiconductor layer 403c which is not processed, the first or third oxide semiconductor
layer does not become a leak path of carriers.

[0190]

Further, an oxide semiconductor layer with high conductivity is used as the
20 second oxide semiconductor layer 404b, whereby a channel of the transistor is formed
in the second oxide semiconductor layer 404b. In the case of the bottom-gate
transistors in FIGS. 9A to 9D, carriers flow in an interface between the second oxide
semiconductor layer 404b and the first oxide semiconductor layer 404a. Further, in the
case of the top-gate transistors in FIGS. 10A to 10D, carriers flow in an interface
25 between the second oxide semiconductor layer 404b and the third oxide semiconductor
layer 404c.

[0191]

In any case, the influence of the localized states due to the oxygen vacancies
can be reduced. Accordingly, a variation in electrical characteristics of a transistor can
30 be suppressed and a transistor with high reliability can be obtained.

[0192]

The structures, methods, and the like described in this embodiment can be combined as appropriate with any of the other structures, methods, and the like described in the other embodiments.

[0193]

5 (Embodiment 4)

A semiconductor device disclosed in this specification can be applied to a variety of electronic appliances (including game machines). Examples of electronic appliances include a television set (also referred to as a television or a television receiver), a monitor of a computer or the like, cameras such as a digital camera and a
10 digital video camera, a digital photo frame, a mobile phone, a portable game machine, a portable information terminal, an audio reproducing device, a game machine (e.g., a pachinko machine or a slot machine), a game console, and the like. Specific examples of these electronic appliances are illustrated in FIGS. 11A to 11C.

[0194]

15 FIG. 11A illustrates a table 9000 having a display portion. In the table 9000, a display portion 9003 is incorporated in a housing 9001 and an image can be displayed on the display portion 9003. Note that the housing 9001 is supported by four leg portions 9002. Further, a power cord 9005 for supplying power is provided for the housing 9001.

20 [0195]

The semiconductor device described in any of the above embodiments can be used in the display portion 9003, so that the electronic appliance can have high reliability.

[0196]

25 The display portion 9003 has a touch-input function. When a user touches displayed buttons 9004 which are displayed on the display portion 9003 of the table 9000 with his/her finger or the like, the user can carry out operation of the screen and input of information. Further, when the table may be made to communicate with home appliances or control the home appliances, the table 9000 may function as a control
30 device which controls the home appliances by operation on the screen. For example, with use of the semiconductor device having an image sensor described in Embodiment 3, the display portion 9003 can function as a touch panel.

[0197]

Further, the screen of the display portion 9003 can be placed perpendicular to a floor with a hinge provided for the housing 9001; thus, the table 9000 can also be used as a television device. When a television device having a large screen is set in a small room, an open space is reduced; however, when a display portion is incorporated in a table, a space in the room can be efficiently used.

[0198]

FIG. 11B illustrates a television set 9100. In the television set 9100, a display portion 9103 is incorporated in a housing 9101 and an image can be displayed on the display portion 9103. Note that the housing 9101 is supported by a stand 9105 here.

[0199]

The television set 9100 can be operated with an operation switch of the housing 9101 or a separate remote controller 9110. Channels and volume can be controlled with an operation key 9109 of the remote controller 9110 so that an image displayed on the display portion 9103 can be controlled. Furthermore, the remote controller 9110 may be provided with a display portion 9107 for displaying data output from the remote controller 9110.

[0200]

The television set 9100 illustrated in FIG. 11B is provided with a receiver, a modem, and the like. With the use of the receiver, the television set 9100 can receive general TV broadcasts. Moreover, when the television set 9100 is connected to a communication network with or without wires via the modem, one-way (from a sender to a receiver) or two-way (between a sender and a receiver or between receivers) information communication can be performed.

[0201]

The semiconductor device described in any of the above embodiments can be used in the display portions 9103 and 9107, so that the television set and the remote controller can have high reliability.

[0202]

FIG. 11C illustrates a computer which includes a main body 9201, a housing 9202, a display portion 9203, a keyboard 9204, an external connection port 9205, a pointing device 9206, and the like.

[0203]

The semiconductor device described in any of the above embodiments can be used in the display portion 9203, so that the computer can have high reliability.

[0204]

5 FIGS. 12A and 12B illustrate a tablet terminal that can be folded. In FIG. 12A, the tablet terminal is opened, and includes a housing 9630, a display portion 9631a, a display portion 9631b, a switch 9034 for switching display modes, a power switch 9035, a switch 9036 for switching to power-saving mode, a clip 9033, and an operation switch 9038.

10 [0205]

The semiconductor device described in any of the above embodiments can be used in the display portion 9631a and the display portion 9631b, so that the tablet terminal can have high reliability.

[0206]

15 Part of the display portion 9631a can be a touch panel region 9632a, and data can be input by touching operation keys 9638 that are displayed. Note that FIG. 9A shows, as an example, that half of the area of the display portion 9631a has only a display function and the other half of the area has a touch panel function. However, the structure of the display portion 9631a is not limited to this, and all the area of the display portion 9631a may have a touch panel function. For example, all the area of the display portion 9631a can display keyboard buttons and serve as a touch panel while the display portion 9631b can be used as a display screen.

[0207]

25 Like the display portion 9631a, part of the display portion 9631b can be a touch panel region 9632b. When a finger, a stylus, or the like touches the place where a button 9639 for switching to keyboard display is displayed in the touch panel, keyboard buttons can be displayed on the display portion 9631b.

[0208]

30 Touch input can be performed concurrently on the touch panel regions 9632a and 9632b.

[0209]

The switch 9034 for switching display modes allows switching between a

landscape mode and a portrait mode, color display and black-and-white display, and the like. With the switch 9036 for switching to power-saving mode, the luminance of display can be optimized in accordance with the amount of external light at the time when the tablet terminal is in use, which is detected with an optical sensor incorporated
5 in the tablet terminal. The tablet terminal may include another detection device such as a sensor for detecting orientation (e.g., a gyroscope or an acceleration sensor) in addition to the optical sensor.

[0210]

Although the display portion 9631a and the display portion 9631b have the
10 same display area in FIG. 12A, an embodiment of the present invention is not limited to this example. The display portion 9631a and the display portion 9631b may have different areas or different display quality. For example, one of them may be a display panel that can display higher-definition images than the other.

[0211]

15 FIG. 12B illustrates the tablet terminal folded, which includes the housing 9630, a solar battery 9633, and a charge and discharge control circuit 9634. Note that FIG. 12B shows an example in which the charge and discharge control circuit 9634 includes the battery 9635 and the DCDC converter 9636.

[0212]

20 Since the tablet can be folded in two, the housing 9630 can be closed when the tablet is not in use. Thus, the display portions 9631a and 9631b can be protected, thereby providing a tablet with high endurance and high reliability for long-term use.

[0213]

The tablet terminal illustrated in FIGS. 12A and 12B can have other functions
25 such as a function of displaying various kinds of data (e.g., a still image, a moving image, and a text image), a function of displaying a calendar, a date, the time, or the like on the display portion, a touch-input function of operating or editing the data displayed on the display portion by touch input, and a function of controlling processing by various kinds of software (programs).

30 [0214]

The solar battery 9633, which is attached on the surface of the tablet terminal, supplies electric power to a touch panel, a display portion, an image signal processor,

and the like. Note that the solar battery 9633 can be provided on one or both surfaces of the housing 9630 and the battery 9635 can be charged efficiently. When a lithium ion battery is used as the battery 9635, there is an advantage of downsizing or the like.

[0215]

5 The structure and operation of the charge and discharge control circuit 9634 illustrated in FIG. 12B are described with reference to a block diagram of FIG. 12C. FIG. 12C illustrates the solar battery 9633, the battery 9635, the DCDC converter 9636, a converter 9637, switches SW1 to SW3, and the display portion 9631. The battery 9635, the DCDC converter 9636, the converter 9637, and the switches SW1 to SW3
10 correspond to the charge and discharge control circuit 9634 in FIG. 12B.

[0216]

 First, an example of operation in the case where power is generated by the solar battery 9633 using external light is described. The voltage of power generated by the solar battery 9633 is raised or lowered by the DCDC converter 9636 so that a voltage
15 for charging the battery 9635 is obtained. When the display portion 9631 is operated with the power from the solar battery 9633, the switch SW1 is turned on and the voltage of the power is raised or lowered by the converter 9637 to a voltage needed for operating the display portion 9631. In addition, when display on the display portion 9631 is not performed, the switch SW1 is turned off and a switch SW2 is turned on so
20 that charge of the battery 9635 may be performed.

[0217]

 Here, the solar battery 9633 is shown as an example of a power generation means; however, there is no particular limitation on a way of charging the battery 9635, and the battery 9635 may be charged with another power generation means such as a
25 piezoelectric element or a thermoelectric conversion element (Peltier element). For example, the battery 9635 may be charged with a non-contact power transmission module that transmits and receives power wirelessly (without contact) to charge the battery or with a combination of other charging means.

[0218]

30 The structures, methods, and the like described in this embodiment can be combined as appropriate with any of the structures, methods, and the like described in the other embodiments.

[Example 1]

[0219]

In this example, the results of CPM measurement performed on a first oxide semiconductor layer, a second oxide semiconductor layer, and a third oxide semiconductor layer which are sequentially stacked are described.

[0220]

A sample A manufactured in this example is described with reference to FIG. 13A.

[0221]

First, as the first oxide semiconductor layer, a 30-nm-thick IGZO layer having an atomic ratio of In:Ga:Zn = 1:3:2 was formed over a glass substrate 700. The IGZO layer having an atomic ratio of In:Ga:Zn = 1:3:2 was formed under the following conditions: a sputtering target of In:Ga:Zn = 1:3:2 (atomic ratio) was used; argon with a flow rate of 30 sccm and oxygen with a flow rate of 15 sccm were supplied as a sputtering gas into a treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was controlled to be 0.4 Pa; and a DC power of 0.5 kW was supplied. Note that the IGZO layer having an atomic ratio of In:Ga:Zn = 1:3:2 was formed at a substrate temperature of 200 °C.

[0222]

Then, as the second oxide semiconductor layer, a 100-nm-thick IGZO layer having an atomic ratio of In:Ga:Zn = 1:1:1 was formed. The IGZO layer having an atomic ratio of In:Ga:Zn = 1:1:1 was formed under the following conditions: a sputtering target of In:Ga:Zn = 1:1:1 (atomic ratio) was used; argon with a flow rate of 30 sccm and oxygen with a flow rate of 15 sccm were supplied as a sputtering gas into a treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was controlled to be 0.4 Pa; and a DC power of 0.5 kW was supplied. Note that the IGZO layer having an atomic ratio of In:Ga:Zn = 1:1:1 was formed at a substrate temperature of 200 °C.

[0223]

Next, the first oxide semiconductor layer and the second oxide semiconductor layer were etched to form an island-shaped first oxide semiconductor layer 701a and an

island-shaped second oxide semiconductor layer 701b.

[0224]

Then, heat treatment was performed. The heat treatment was performed at 450 °C under a nitrogen atmosphere for one hour, and then in dry air (under a dry atmosphere) for one hour.

[0225]

Next, a 100-nm-thick tungsten film was formed over the island-shaped first oxide semiconductor layer 701a and the island-shaped second oxide semiconductor layer 701b. The tungsten film was formed under the following conditions: a sputtering target of tungsten was used; argon with a flow rate of 80 sccm was supplied as a sputtering gas into a treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was controlled to be 0.8 Pa; and a DC power of 1 kW was supplied. Note that the tungsten film was formed at 230 °C. Then, the tungsten film was selectively etched to form electrode layers 705a and 705b.

[0226]

Next, as the third oxide semiconductor layer 701c, a 30-nm-thick IGZO layer having an atomic ratio of In:Ga:Zn = 1:3:2 was formed over the second oxide semiconductor layer 701b and the electrode layers 705a and 705b. The IGZO layer having an atomic ratio of In:Ga:Zn = 1:3:2 was formed under the following conditions: a sputtering target of In:Ga:Zn = 1:3:2 (atomic ratio) was used; argon with a flow rate of 30 sccm and oxygen with a flow rate of 15 sccm were supplied as a sputtering gas into a treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was controlled to be 0.4 Pa; and a DC power of 0.5 kW was supplied. Note that the IGZO layer having an atomic ratio of In:Ga:Zn = 1:3:2 was formed at a substrate temperature of 200 °C.

[0227]

Next, as an insulating film 706, a 300-nm-thick silicon oxide film was formed over the third oxide semiconductor layer 701c. The silicon oxide film was formed under the following conditions: a sputtering target of silicon oxide was used; oxygen with a flow rate of 50 sccm was supplied as a sputtering gas into a treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was controlled to be 0.4

Pa; and a DC power of 1.5 kW was supplied. Note that the silicon oxide film was formed at a substrate temperature of 100 °C.

[0228]

After the formation of the silicon oxide film, heat treatment was performed.

5 The heat treatment was performed at 300 °C in dry air (under a dry atmosphere) for one hour.

[0229]

Through the above process, the sample A illustrated in FIG. 13A was manufactured.

10 [0230]

Next, a sample B is described with reference to FIG. 13B.

[0231]

First, as the first oxide semiconductor layer, a 30-nm-thick IGZO layer having an atomic ratio of In:Ga:Zn = 1:3:2 was formed over a glass substrate 700 in a manner similar to the sample A. The IGZO layer having an atomic ratio of In:Ga:Zn = 1:3:2 was formed under the following conditions: a sputtering target of In:Ga:Zn = 1:3:2 (atomic ratio) was used; argon with a flow rate of 30 sccm and oxygen with a flow rate of 15 sccm were supplied as a sputtering gas into a treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was controlled to be 0.4 Pa; and a DC power of 0.5 kW was supplied. Note that the IGZO layer having an atomic ratio of In:Ga:Zn = 1:3:2 was formed at a substrate temperature of 200 °C.

20

[0232]

Then, as the second oxide semiconductor layers 701b (701b1, 701b2), a 50-nm-thick IGZO layer having an atomic ratio of In:Ga:Zn = 3:1:2 and a 50-nm-thick IGZO layer having an atomic ratio of In:Ga:Zn = 1:1:1 were formed. The IGZO layer having an atomic ratio of In:Ga:Zn = 3:1:2 was formed under the following conditions: a sputtering target of In:Ga:Zn = 3:1:2 (atomic ratio) was used; oxygen with a flow rate of 45 sccm was supplied as a sputtering gas into a treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was controlled to be 0.4 Pa; and a DC power of 0.5 kW was supplied. Note that the IGZO layer having an atomic ratio of In:Ga:Zn = 3:1:2 was formed at a substrate temperature of 200 °C. The IGZO layer

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having an atomic ratio of In:Ga:Zn = 1:1:1 was formed under the following conditions: a sputtering target of In:Ga:Zn = 1:1:1 (atomic ratio) was used; oxygen with a flow rate of 45 sccm was supplied as a sputtering gas into a treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was controlled to be 0.4 Pa; and a DC power of 0.5 kW was supplied.

[0233]

Next, the first oxide semiconductor layer and the second oxide semiconductor layer were etched to form an island-shaped first oxide semiconductor layer 701a and island-shaped second oxide semiconductor layers 701b (701b1, 701b2).

[0234]

Then, heat treatment was performed. The heat treatment was performed at 450 °C under a nitrogen atmosphere for one hour, and then in dry air (under a dry atmosphere) for one hour.

[0235]

Next, a 100-nm-thick tungsten film was formed over the island-shaped first oxide semiconductor layer 701a and the island-shaped second oxide semiconductor layers 701b (701b1, 701b2). The tungsten film was formed under the following conditions: a sputtering target of tungsten was used; argon with a flow rate of 80 sccm was supplied as a sputtering gas into a treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was controlled to be 0.8 Pa; and a DC power of 1 kW was supplied. Note that the tungsten film was formed at 230 °C. Then, the tungsten film was selectively etched to form electrode layers 705a and 705b.

[0236]

Next, as the third oxide semiconductor layer 701c, a 30-nm-thick IGZO layer having an atomic ratio of In:Ga:Zn = 1:3:2 was formed over the second oxide semiconductor layers 701b (701b1, 701b2) and the electrode layers 705a and 705b. The IGZO layer having an atomic ratio of In:Ga:Zn = 1:3:2 was formed under the following conditions: a sputtering target of In:Ga:Zn = 1:3:2 (atomic ratio) was used; argon with a flow rate of 30 sccm and oxygen with a flow rate of 15 sccm were supplied as a sputtering gas into a treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was controlled to be 0.4 Pa; and a DC power of 0.5 kW was

supplied. Note that the IGZO layer having an atomic ratio of In:Ga:Zn = 1:3:2 was formed at a substrate temperature of 200 °C.

[0237]

Next, as an insulating film 706, a 300-nm-thick silicon oxide film was formed over the third oxide semiconductor layer 701c. The silicon oxide film was formed under the following conditions: a sputtering target of silicon oxide was used; oxygen with a flow rate of 50 sccm was supplied as a sputtering gas into a treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was controlled to be 0.4 Pa; and a DC power of 1.5 kW was supplied. Note that the silicon oxide film was formed at a substrate temperature of 100 °C.

[0238]

After the formation of the silicon oxide film, heat treatment was performed. The heat treatment was performed at 300 °C in dry air (under a dry atmosphere) for one hour.

[0239]

Through the above process, the sample B illustrated in FIG. 13B was manufactured.

[0240]

FIGS. 14A and 14B and FIGS. 15A and 15B show the results of CPM measurement performed on the sample A and the sample B. In FIGS. 14A and 15A, a thick line represents a curve of the absorption coefficient of each sample, a thin line represents the absorption coefficient optically measured, and a thin dotted line represents a tangent. FIG. 14A shows the curve of the absorption coefficient of the sample A and FIG. 14B shows the absorption coefficient obtained by removing the absorption coefficient due to the band tail from the curve of the absorption coefficient, that is, the absorption coefficient due to defects. FIG. 15A shows the curve of the absorption coefficient of the sample B and FIG. 15B shows the absorption coefficient due to defects.

[0241]

In FIGS. 14A and 15A, the horizontal axis indicates the photon energy, and the vertical axis indicates the absorption coefficient. In FIGS. 14B and 15B, the horizontal

axis indicates the absorption coefficient, and the vertical axis indicates the photon energy. On the vertical axes in FIGS. 14B and 15B, the bottom of the conduction band of the oxide semiconductor layer is set to 0 eV, and the top of the valence band is set to 3.15 eV. In FIG. 14B, the curve indicated by a solid line corresponds to the localized states of the sample A, and absorption due to the localized states is seen in an energy range of 1.5 eV to 2.3 eV. When the values at each energy level are integrated, it is found that the absorption coefficient due to the localized states of the sample A is 2.02×10^{-4} /cm. Further, in FIG. 15B, the curve indicated by a solid line corresponds to the localized states of the sample B, and absorption due to the localized states is seen in an energy range of 1.5 eV to 2.3 eV. When the values at each energy level are integrated, it is found that the absorption coefficient due to the localized states of the sample B is 2.84×10^{-3} /cm.

[0242]

Consequently, it is found that the second oxide semiconductor layer 701b in which the proportion of indium is high is sandwiched between the first oxide semiconductor layer 701a and the third oxide semiconductor layer 701c, whereby the influence of the oxygen vacancies can be reduced. As a result, it is thought that the absorption coefficient due to the localized states measured by the CPM can be the above value.

[Example 2]

[0243]

In this example, the results of evaluating the reliability of the transistor including the oxide semiconductor stacked film of one embodiment of the present invention.

[0244]

A sample C and a sample D each including the transistor including the oxide semiconductor stacked film of one embodiment of the present invention are described with reference to FIGS. 16A to 16D.

[0245]

First, a manufacturing process of the sample C including a transistor is described. As a substrate 800, a silicon substrate was used, and as a base film 808, a

100-nm-thick silicon oxide film and a 300-nm-thick silicon oxynitride film were formed over the substrate 800. The silicon oxide film was formed by performing thermal oxidation treatment at 950 °C in an oxidizing atmosphere containing chlorine. Further, the silicon oxynitride film was formed by a CVD method.

5 [0246]

Next, by performing CMP treatment on a surface of the base film 808, planarization treatment was performed on the surface of the base film 808.

[0247]

After the planarization treatment, heat treatment was performed. The heat
10 treatment was performed at 450 °C in a vacuum for one hour. After that, oxygen ions were added to the base film 808 by an ion implantation method. Note that the conditions of the oxygen ion implantation were as follows: an acceleration voltage of 60 kV and a dosage of 2.0×10^{16} ions/cm².

[0248]

15 Next, as the first oxide semiconductor layer 803a, a 5-nm-thick IGZO layer having an atomic ratio of In:Ga:Zn = 1:3:2 was formed. The IGZO layer having an atomic ratio of In:Ga:Zn = 1:3:2 was formed under the following conditions: a sputtering target of In:Ga:Zn = 1:3:2 (atomic ratio) was used; argon with a flow rate of 30 sccm and oxygen with a flow rate of 15 sccm were supplied as a sputtering gas into
20 treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was controlled to be 0.4 Pa; and a DC power of 0.5 kW was supplied. Note that the IGZO layer having an atomic ratio of In:Ga:Zn = 1:3:2 was formed at a substrate temperature of 200 °C.

[0249]

25 Then, as the second oxide semiconductor layer 803b, a 5-nm-thick IGZO layer having an atomic ratio of In:Ga:Zn = 3:1:2 was formed. The IGZO layer having an atomic ratio of In:Ga:Zn = 3:1:2 was formed under the following conditions: a sputtering target of In:Ga:Zn = 3:1:2 (atomic ratio) was used; argon with a flow rate of 30 sccm and oxygen with a flow rate of 15 sccm were supplied as a sputtering gas into
30 treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was controlled to be 0.4 Pa; and a DC power of 0.5 kW was supplied. Note that the IGZO

layer having an atomic ratio of In:Ga:Zn = 3:1:2 was formed at a substrate temperature of 200 °C.

[0250]

Then, as the third oxide semiconductor layer 803c, a 5-nm-thick IGZO layer
5 having an atomic ratio of In:Ga:Zn = 1:1:1 was formed. The IGZO layer having an atomic ratio of In:Ga:Zn = 1:1:1 was formed under the following conditions: a sputtering target of In:Ga:Zn = 1:1:1 (atomic ratio) was used; argon with a flow rate of 30 sccm and oxygen with a flow rate of 15 sccm were supplied as a sputtering gas into a treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was
10 controlled to be 0.4 Pa; and a DC power of 0.5 kW was supplied. Note that the IGZO layer having an atomic ratio of In:Ga:Zn = 1:1:1 was formed at a substrate temperature of 300 °C.

[0251]

Note that the first oxide semiconductor layer 803a, the second oxide
15 semiconductor layer 803b, and the third oxide semiconductor layer 803c were successively formed without exposure to the air. The above steps are illustrated in FIG. 16A.

[0252]

Then, heat treatment was performed after the formation of the third oxide
20 semiconductor layer 803c. The heat treatment was performed at 450 °C under a nitrogen atmosphere for one hour, and then under an oxygen atmosphere for one hour.

[0253]

Next, the first oxide semiconductor layer 803a, the second oxide
semiconductor layer 803b, and the third oxide semiconductor layer 803c were processed
25 into the first oxide semiconductor layer 804a, the second oxide semiconductor layer 804b, and the third oxide semiconductor layer 804c each having an island shape by etching treatment using a photolithography process, so that the oxide semiconductor stacked film 804 was formed (see FIG. 16B).

[0254]

30 Next, a 100-nm-thick tungsten film was formed over the oxide semiconductor stacked film 804. The tungsten film was formed under the following conditions: a

sputtering target of tungsten was used; argon with a flow rate of 80 sccm was supplied as a sputtering gas into a treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was controlled to be 0.8 Pa; and the DC power of 1 kW was supplied. Note that the tungsten film was formed at 230 °C. Then, the tungsten film was selectively etched to form a source electrode layer 805a and a drain electrode layer 805b (see FIG. 16C).

[0255]

Then, as a gate insulating film 809, a 20-nm-thick silicon oxynitride film was formed over the source electrode layer 805a and the drain electrode layer 805b by a CVD method.

[0256]

Next, a 30-nm-thick tantalum nitride film and a 135-nm-thick tungsten film were formed over the gate insulating film 809. The tantalum nitride film was formed under the following conditions: a sputtering target of tantalum nitride was used; argon with a flow rate of 50 sccm and nitrogen with a flow rate of 10 sccm were supplied as a sputtering gas into a treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was controlled to be 0.6 Pa; and the DC power of 1 kW was supplied. Note that when the tantalum nitride film was formed, a substrate temperature was set to room temperature. Further, the tungsten film was formed under the following conditions: a sputtering target of tungsten was used; argon with a flow rate of 100 sccm was supplied as a sputtering gas into a treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was controlled to be 2.0 Pa; and the DC power of 4 kW was supplied. Note that the tungsten film was formed at 230 °C. Then, the tantalum nitride film and the tungsten film were selectively etched to form a gate electrode layer 810.

[0257]

Next, phosphorus (P) ions were added to the oxide semiconductor stacked film 804 by an ion implantation method using the gate electrode layer 810, the source electrode layer 805a, and the drain electrode layer 805b as masks. The conditions of the phosphorus (P) ion implantation were as follows: an acceleration voltage of 40 kV and a dosage of 1.0×10^{15} ions/cm².

[0258]

Next, as an insulating film 811, a 70-nm-thick aluminum oxide film was formed by a sputtering method and a 300-nm-thick silicon oxynitride film was formed by a CVD method. The aluminum oxide film was formed under the following conditions: argon with a flow rate of 25 sccm and oxygen with a flow rate of 25 sccm were supplied as a sputtering gas into a treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was controlled to be 0.4 Pa; and the DC power of 2.5 kW was supplied. Note that the aluminum oxide film was formed at a substrate temperature of 250 °C.

10 [0259]

Next, the insulating film 811 was selectively etched to form openings which reach the source electrode layer 805a and the drain electrode layer 805b. After that, a 50-nm-thick titanium film, a 200-nm-thick aluminum film, and a 50-nm-thick titanium film were formed. The titanium films were formed under the following conditions: argon with a flow rate of 20 sccm was supplied as a sputtering gas into a treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was 0.1 Pa; and the DC power of 12 kW was supplied. Note that when the titanium film was formed, a substrate temperature was set to at room temperature. Further, the aluminum film was formed under the following conditions: argon with a flow rate of 50 sccm was supplied as a sputtering gas into a treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was 0.4 Pa; and the DC power of 1 kW was supplied. Then, the titanium film, the aluminum film, and the titanium film were selectively etched to form a wiring layer 812a and a wiring layer 812b (see FIG. 16D).

[0260]

25 Through the above process, the sample C including the transistor was manufactured.

[0261]

Next, a manufacturing process of the sample D including a transistor is described.

30 [0262]

The sample D is the same as the sample C except for the structure of the oxide semiconductor stacked film 804; thus, only differences between the sample C and the

sample D are described.

[0263]

After oxygen was added to the base film 808, the first oxide semiconductor layer 803a, the second oxide semiconductor layer 803b, and the third oxide semiconductor layer 803c were formed.

[0264]

As the first oxide semiconductor layer 803a, a 5-nm-thick IGZO layer having an atomic ratio of In:Ga:Zn = 1:3:2 was formed. The IGZO layer having an atomic ratio of In:Ga:Zn = 1:3:2 was formed under the following conditions: a sputtering target of In:Ga:Zn = 1:3:2 (atomic ratio) was used; argon with a flow rate of 30 sccm and oxygen with a flow rate of 15 sccm were supplied as a sputtering gas into a treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was controlled to be 0.4 Pa; and a DC power of 0.5 kW was supplied. Note that the IGZO layer having an atomic ratio of In:Ga:Zn = 1:3:2 was formed at a substrate temperature of 200 °C.

[0265]

Then, as the second oxide semiconductor layer 803b, a 15-nm-thick IGZO layer having an atomic ratio of In:Ga:Zn = 3:1:2 was formed. The IGZO layer having an atomic ratio of In:Ga:Zn = 3:1:2 was formed under the following conditions: a sputtering target of In:Ga:Zn = 3:1:2 (atomic ratio) was used; argon with a flow rate of 30 sccm and oxygen with a flow rate of 15 sccm were supplied as a sputtering gas into a treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was controlled to be 0.4 Pa; and a DC power of 0.5 kW was supplied. Note that the IGZO layer having an atomic ratio of In:Ga:Zn = 3:1:2 was formed at a substrate temperature of 300 °C.

[0266]

Then, as the third oxide semiconductor layer 803c, a 5-nm-thick IGZO layer having an atomic ratio of In:Ga:Zn = 1:1:1 was formed. The IGZO layer having an atomic ratio of In:Ga:Zn = 1:1:1 was formed under the following conditions: a sputtering target of In:Ga:Zn = 1:1:1 (atomic ratio) was used; argon with a flow rate of 30 sccm and oxygen with a flow rate of 15 sccm were supplied as a sputtering gas into a

treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was controlled to be 0.4 Pa; and a DC power of 0.5 kW was supplied. Note that the IGZO layer having an atomic ratio of In:Ga:Zn = 1:1:1 was formed at a substrate temperature of 200 °C.

5 [0267]

Note that the first oxide semiconductor layer 803a, the second oxide semiconductor layer 803b, and the third oxide semiconductor layer 803c were successively formed without exposure to the air.

[0268]

10 Steps after that were performed in a manner similar to the sample C, whereby the sample D including the transistor was manufactured.

[0269]

Next, a manufacturing process of a sample E as a comparative example including a transistor is described.

15 [0270]

The sample E is the same as the sample C except for the use of a single oxide semiconductor layer instead of stacked oxide semiconductor layers; thus, only differences between the sample C and the sample E are described.

[0271]

20 After oxygen was added to the base film 808, the oxide semiconductor layer was formed.

[0272]

Then, as the oxide semiconductor layer, a 15-nm-thick IGZO layer having an atomic ratio of In:Ga:Zn = 1:1:1 was formed. The IGZO layer having an atomic ratio of In:Ga:Zn = 1:1:1 was formed under the following conditions: a sputtering target of In:Ga:Zn = 1:1:1 (atomic ratio) was used; argon with a flow rate of 30 sccm and oxygen with a flow rate of 15 sccm were supplied as a sputtering gas into a treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was controlled to be 0.4 Pa; and a DC power of 0.5 kW was supplied. Note that the IGZO layer having an atomic ratio of In:Ga:Zn = 1:1:1 was formed at a substrate temperature of 200 °C.

30

[0273]

Steps after that were performed in a manner similar to the sample C, whereby the sample E including the transistor was manufactured.

[0274]

The channel length (L) of each of the transistors included in the sample C, the sample D, and the sample E was 0.6 μm and the channel width (W) thereof was 1.0 μm .

[0275]

One of methods for examining reliability of transistors is a GBT test. The GBT test is one kind of accelerated test and a change in characteristics, caused by long-term use, of transistors can be evaluated in a short time. In particular, the amount of shift in threshold voltage of the transistor between before and after a GBT test is an important indicator for examining reliability. The smaller the shift in the threshold voltage between before and after a GBT test is, the higher the reliability of the transistor is.

[0276]

The temperature of a substrate over which a transistor is formed is set at a fixed temperature. A source and a drain of the transistor are set at the same potential, and a gate is supplied with a potential different from those of the source and the drain for a certain period. The temperature of the substrate may be determined depending on the purpose of the test. Further, the potential applied to the gate is higher than the potential of the source and the drain (the potential of the source and the drain is the same) in a "+GBT test" while the potential applied to the gate is lower than the potential of the source and the drain (the potential of the source and the drain is the same) in a "-GBT test."

[0277]

Strength of the GBT test may be determined based on the temperature of a substrate and electric field intensity and time period of application of the electric field to a gate insulating layer. The electric field intensity in the gate insulating layer is determined as the value of a potential difference between a gate, and a source and a drain divided by the value of the thickness of the gate insulating layer.

[0278]

In this example, a positive GBT test was performed on each of the transistors

included in the sample C, the sample D, and the sample E. First, initial V_g - I_d characteristics of the transistor were measured. Here, a change in characteristics of the source-drain current (hereinafter, referred to as the drain current), that is, V_g - I_d characteristics were measured under the conditions as follows: the substrate temperature
5 was 40 °C, the voltages between the source and the drain (hereinafter, referred to as the drain voltage) were 0.1 V and 3.3 V, and the voltage between the source and the gate electrode (hereinafter, referred to as the gate voltage) was changed from -4 V to +4 V.

[0279]

Next, the substrate temperature was raised to 150 °C, and then, the potentials of
10 the source and the drain of the transistor were set to 0 V. Then, the voltage of +3.3 V was kept being applied to the gate electrode for one hour so that the intensity of the electric field applied to the gate insulating film was +1.65 MV/cm. After that, the substrate temperature was lowered to 40 °C while voltage was continuously applied to the gate electrode, and the source and the drain. After the substrate temperature was
15 reached to 40 °C, the application of voltage to the gate electrode, and the source and the drain was stopped.

[0280]

Then, V_g - I_d characteristics were measured under the same conditions as those for the measurement of the initial characteristics.

20 [0281]

Next, a negative GBT test was performed on each of the transistors included in the sample C, the sample D, and the sample E. First, initial V_g - I_d characteristics of the transistor were measured. In a manner similar to the positive GBT test, a change in characteristics of the drain current, that is, V_g - I_d characteristics were measured under
25 the conditions as follows: the substrate temperature was 40 °C, the drain voltages were 0.1 V and 3.3 V, and the gate voltage was changed from -4 V to +4 V.

[0282]

Next, the substrate temperature was raised to 150 °C, and then, the potentials of the source and the drain of the transistor were set to 0 V. Then, -3.3 V was kept being
30 applied to the gate electrode for one hour so that the intensity of the electric field applied to the gate insulating film was -1.65 MV/cm. After that, the substrate

temperature was lowered to 40 °C while voltage was continuously applied to the gate electrode, and the source and the drain. After the substrate temperature was reached to 40 °C, the application of voltage to the gate electrode, and the source and the drain was stopped.

5 [0283]

Then, V_g - I_d characteristics were measured under the same conditions as those for the measurement of the initial characteristics.

[0284]

FIGS. 17A and 17B, FIGS. 18A and 18B, and FIGS. 19A and 19B show results of the positive GBT test and the negative GBT test of the transistors included in the sample C, the sample D, and the sample E. FIG. 17A shows results of the positive GBT test of the transistor included in the sample C and FIG. 17B shows results of the negative GBT test of the transistor included in the sample C. FIG. 18A shows results of the positive GBT test of the transistor included in the sample D and FIG. 18B shows results of the negative GBT test of the transistor included in the sample D. FIG. 19A shows results of the positive GBT test of the transistor included in the sample E and FIG. 19B shows results of the negative GBT test of the transistor included in the sample E.

[0285]

In FIGS. 17A and 17B, FIGS. 18A and 18B, and FIGS. 19A and 19B, a thin line represents results before a GBT test and a thick line represents results after the GBT test.

[0286]

As shown in FIGS. 17A and 17B and FIGS. 18A and 18B, a change in the threshold voltage through the positive GBT test and the negative GBT test is hardly observed in each of the transistors included in the sample C and the sample D. In contrast, as illustrated in FIGS. 19A and 19B, in the transistor included in the sample E, a change in the threshold voltage due to the positive GBT test is found. Further, in the transistor included in the sample E, a reduction in on-state current is also found. Consequently, it was confirmed that the degree of changes in the threshold voltage through the GBT test is small and reliability is high in the transistors included in the example C and the sample D.

[Example 3]

[0287]

In this example, the measurement results of the conductivity of the oxide semiconductor included in the oxide semiconductor stacked film of one embodiment of the present invention are described.

[0288]

In this example, an oxide semiconductor layer using a target having an atomic ratio of In:Ga:Zn = 1:1:1, an oxide semiconductor layer using a target having an atomic ratio of In:Ga:Zn = 3:1:2, and an oxide semiconductor layer using a target having an atomic ratio of In:Ga:Zn = 1:3:2 were formed. After heat treatment was performed on the formed oxide semiconductor layers, the conductivities of the oxide semiconductor layers were measured by equipment used for Hall effect measurement. Further, a silicon oxide film was further formed over each of the oxide semiconductor layers and heat treatment was performed thereon, and then the conductivities of the oxide semiconductor layers were measured. Note that in this example, an IGZO layer having an atomic ratio of In:Ga:Zn = 1:1:1, an IGZO layer having an atomic ratio of In:Ga:Zn = 3:1:2, and an IGZO layer having an atomic ratio of In:Ga:Zn = 1:3:2 are referred to as a first IGZO layer, a second IGZO layer, and a third IGZO layer, respectively.

[0289]

A 100-nm-thick first IGZO layer was formed over a glass substrate. The first IGZO layer was formed under the following conditions: a sputtering target of In:Ga:Zn = 1:1:1 (atomic ratio) was used; oxygen with a flow rate of 45 sccm was supplied as a sputtering gas into a treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was controlled to be 0.4 Pa; and a DC power of 0.5 kW was supplied. Note that the first IGZO layer was formed at a substrate temperature of 300 °C.

[0290]

Then, heat treatment was performed. The heat treatment was performed at 450 °C under a nitrogen atmosphere for one hour, and then in dry air (under a dry atmosphere) for one hour.

[0291]

Next, a 100-nm-thick tungsten film was formed over the first IGZO layer.

The tungsten film was formed under the following conditions: a sputtering target of tungsten was used; argon with a flow rate of 80 sccm was supplied as a sputtering gas into a treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was controlled to be 0.8 Pa; and a DC power of 1 kW was supplied. Note
5 that the tungsten film was formed at 230 °C. Then, the tungsten film was selectively etched to form an electrode layer.

[0292]

Here, the conductivity of the first IGZO layer was measured by the equipment used for Hall effect measurement.

10 [0293]

Next, a silicon oxide film was formed over the first IGZO layer and the electrode layer. The silicon oxide film was formed under the following conditions: a sputtering target of silicon oxide was used; oxygen with a flow rate of 50 sccm was supplied as a sputtering gas into a treatment chamber of a sputtering apparatus; the
15 pressure in the treatment chamber was controlled to be 0.4 Pa; and a DC power of 1.5 kW was supplied. Note that the silicon oxide film was formed at a substrate temperature of 100 °C.

[0294]

After the formation of the silicon oxide film, heat treatment was performed.
20 The heat treatment was performed at 300 °C in dry air (under a dry atmosphere) for one hour.

[0295]

After that, the conductivity of the first IGZO layer was measured by the equipment used for Hall effect measurement.

25 [0296]

In a manner similar to the first IGZO layer, a 100-nm-thick second IGZO layer was formed over the glass substrate. The second IGZO layer was formed under the following conditions: a sputtering target of In:Ga:Zn = 3:1:2 (atomic ratio) was used; oxygen with a flow rate of 45 sccm was supplied as a sputtering gas into a treatment
30 chamber of a sputtering apparatus; the pressure in the treatment chamber was controlled to be 0.4 Pa; and a DC power of 0.5 kW was supplied. Note that the second IGZO

layer was formed at a substrate temperature of 300 °C.

[0297]

Here, the conductivity of the second IGZO layer was measured by the equipment used for Hall effect measurement.

5 [0298]

Next, a silicon oxide film was formed over the first and second IGZO layers and the electrode layer. The silicon oxide film was formed under the following conditions: a sputtering target of silicon oxide was used; oxygen with a flow rate of 50 sccm was supplied as a sputtering gas into a treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was controlled to be 0.4 Pa; and a DC power of 1.5 kW was supplied. Note that the silicon oxide film was formed at a substrate temperature of 100 °C.

[0299]

After the formation of the silicon oxide film, heat treatment was performed.

15 The heat treatment was performed at 300 °C in dry air (under a dry atmosphere) for one hour.

[0300]

After that, the conductivity of the second IGZO layer was measured by the equipment used for Hall effect measurement.

20 [0301]

In a manner similar to the first IGZO layer and the second IGZO layer, a 100-nm-thick third IGZO layer was formed over the glass substrate. The third IGZO layer was formed under the following conditions: a sputtering target of In:Ga:Zn = 1:3:2 (atomic ratio) was used; oxygen with a flow rate of 45 sccm was supplied as a sputtering gas into a treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was controlled to be 0.4 Pa; and a DC power of 0.5 kW was supplied. Note that the third IGZO layer was formed at a substrate temperature of 200 °C.

[0302]

Here, the conductivity of the third IGZO layer was measured by the equipment used for Hall effect measurement.

30

[0303]

Next, a silicon oxide film was formed over the first, second, and third IGZO layers and the electrode layer. The silicon oxide film was formed under the following conditions: a sputtering target of silicon oxide was used; oxygen with a flow rate of 50 sccm was supplied as a sputtering gas into a treatment chamber of a sputtering apparatus; the pressure in the treatment chamber was controlled to be 0.4 Pa; and a DC power of 1.5 kW was supplied. Note that the silicon oxide film was formed at a substrate temperature of 100 °C.

[0304]

After the formation of the silicon oxide film, heat treatment was performed. The heat treatment was performed at 200 °C in dry air (under a dry atmosphere) for one hour.

[0305]

After that, the conductivity of the third IGZO layer was measured by the equipment used for Hall effect measurement.

15 [0306]

Table 1 shows the measurement results of the conductivities of the first IGZO layer, the second IGZO layer, and the third IGZO layer by using the equipment used for Hall effect measurement.

[0307]

20 [Table 1]

	Hall effect measurement 1 Conductivity[S/cm]	Hall effect measurement 2 Conductivity[S/cm]
First IGZO layer	4.5×10^{-1}	6.7×10^{-5}
Second IGZO layer	9.7	2
Third IGZO layer	8.1×10^{-9} (below the lower limit of measurement)	1.6×10^{-8} (below the lower limit of measurement)

[0308]

As seen from Table 1, the conductivities of the first IGZO layer and the second IGZO layer can be higher than that of the third IGZO layer.

EXPLANATION OF REFERENCE

[0309]

100: substrate, 101: oxide semiconductor stacked film, 101a: oxide semiconductor layer,
101b: oxide semiconductor layer, 101b1: oxide semiconductor layer, 101b2: oxide
5 semiconductor layer, 101c: oxide semiconductor layer, 111: oxide semiconductor layer,
112a: oxide semiconductor layer, 112b: oxide semiconductor layer, 113a: oxide
semiconductor layer, 113b: oxide semiconductor layer, 113c: oxide semiconductor layer,
121: insulating film, 122: insulating film, 201: lamp, 202: monochromator, 203: filter,
204: beam splitter, 205: photodiode, 206: direct-current power source, 207: lock-in
10 amplifier, 208: calculator, 209: lock-in amplifier, 210: sample, 211a: electrode, 211b:
electrode, 310: transistor, 320: transistor, 330: transistor, 340: transistor, 350: transistor,
360: transistor, 370: transistor, 380: transistor, 390: transistor, 400: substrate, 401: gate
electrode layer, 402: gate insulating film, 403a: oxide semiconductor layer, 403b: oxide
semiconductor layer, 403c: oxide semiconductor layer, 404: oxide semiconductor
15 stacked film, 404a: oxide semiconductor layer, 404b: oxide semiconductor layer, 404c:
oxide semiconductor layer, 405a: source electrode layer, 405b: drain electrode layer,
406: insulating film, 407: electrode layer, 408: insulating film, 409: gate insulating film,
410: gate electrode layer, 411: oxide semiconductor layer, 450: transistor, 460: transistor,
700: glass substrate, 701a: oxide semiconductor layer, 701b: oxide semiconductor layer,
20 701c: oxide semiconductor layer, 705a: electrode layer, 705b: electrode layer, 706:
insulating film, 800: substrate, 803a: oxide semiconductor layer, 803b: oxide
semiconductor layer, 803c: oxide semiconductor layer, 804: oxide semiconductor
stacked film, 804a: oxide semiconductor layer, 804c: oxide semiconductor layer, 805a:
source electrode layer, 805b: drain electrode layer, 808: base film, 809: gate insulating
25 film, 810: gate electrode layer, 811: insulating film, 812a: wiring layer, 812b: wiring
layer, 9000: table, 9001: housing, 9002: leg portion, 9003: display portion, 9004:
displayed button, 9005: power cord, 9033: clip, 9034: switch, 9035: power button,
9036: switch, 9038: operation button, 9100: television set, 9101: housing, 9103: display
portion, 9105: stand, 9107: display portion, 9109: operation key, 9110: remote controller,
30 9201: main body, 9202: housing, 9203: display portion, 9204: keyboard, 9205: external
connection port, 9206: pointing device, 9630: housing, 9631: display portion, 9631a:
display portion, 9631b: display portion, 9632a: region, 9632b: region, 9633: solar

battery, 9634: charge and discharge control circuit, 9635: battery, 9636: DCDC converter, 9637: converter, 9638: operation key, 9639: button.

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5 2012-173388 filed with Japan Patent Office on August 3, 2012, the entire contents of which are hereby incorporated by reference.

CLAIMS

1. An oxide semiconductor stacked film comprising a first oxide semiconductor layer, a second oxide semiconductor layer, and a third oxide semiconductor layer which are sequentially stacked and each of which includes indium, gallium, and zinc,
5 wherein the content percentage of indium in the second oxide semiconductor layer is higher than the content percentage of indium in the first oxide semiconductor layer and the content percentage of indium in the third oxide semiconductor layer, and
wherein an absorption coefficient of the oxide semiconductor stacked film,
10 which is measured by a CPM, is lower than or equal to $3 \times 10^{-3}/\text{cm}$ in an energy range of 1.5 eV to 2.3 eV.
2. The oxide semiconductor stacked film according to claim 1, wherein the second oxide semiconductor layer includes a crystal part whose c-axis is substantially
15 perpendicular to a surface of the oxide semiconductor stacked film.
3. The oxide semiconductor stacked film according to claim 1, wherein in the second oxide semiconductor layer, the content percentage of indium is higher than the content percentage of gallium.
20
4. The oxide semiconductor stacked film according to claim 1, wherein the second oxide semiconductor layer has a stacked-layer structure.
5. The oxide semiconductor stacked film according to claim 1, wherein the
25 conductivity of the second oxide semiconductor layer is higher than the conductivity of the first oxide semiconductor layer and the conductivity of the third oxide semiconductor layer.
6. A semiconductor device comprising:
30 a first gate electrode layer;
a first insulating film over the first gate electrode layer;
an oxide semiconductor stacked film overlapping with the first gate electrode

layer with the first insulating film interposed therebetween; and

a pair of electrode layers in contact with the oxide semiconductor stacked film,
wherein the oxide semiconductor stacked film includes a first oxide
semiconductor layer, a second oxide semiconductor layer, and a third oxide
5 semiconductor layer which are sequentially stacked and each of which contains indium,
gallium, and zinc,

wherein the content percentage of indium in the second oxide semiconductor
layer is higher than the content percentage of indium in the first oxide semiconductor
layer and the content percentage of indium in the third oxide semiconductor layer, and

10 wherein an absorption coefficient of a channel formation region in the oxide
semiconductor stacked film, which is measured by the CPM, is lower than or equal to $3 \times 10^{-3}/\text{cm}$ in an energy range of 1.5 eV to 2.3 eV.

7. The semiconductor device according to claim 6, wherein the second oxide
15 semiconductor layer includes a crystal part whose c-axis is substantially perpendicular
to a surface of the oxide semiconductor stacked film.

8. The semiconductor device according to claim 6, wherein in the second oxide
semiconductor layer, the content percentage of indium is higher than the content
20 percentage of gallium.

9. The semiconductor device according to claim 6, wherein the second oxide
semiconductor layer has a stacked-layer structure.

25 10. The semiconductor device according to claim 6, wherein the conductivity
of the second oxide semiconductor layer is higher than the conductivity of the first
oxide semiconductor layer and the conductivity of the third oxide semiconductor layer.

11. The semiconductor device according to claim 6 further comprising an oxide
30 insulating film over the pair of electrode layers and the oxide semiconductor stacked
film.

12. The semiconductor device according to claim 6 further comprising:
a second insulating film over the pair of electrode layers and the oxide semiconductor stacked film, and
a second gate electrode layer overlapping with the oxide semiconductor stacked
5 film with the second insulating film interposed therebetween.

13. A semiconductor device comprising:
an oxide semiconductor stacked film;
a pair of electrode layers in contact with the oxide semiconductor stacked film;
10 a gate insulating film over the oxide semiconductor stacked film; and
a gate electrode layer overlapping with the oxide semiconductor stacked film
with the gate insulating film interposed therebetween,
wherein the oxide semiconductor stacked film includes a first oxide
semiconductor layer, a second oxide semiconductor layer, and a third oxide
15 semiconductor layer which are sequentially stacked and each of which contains indium,
gallium, and zinc,
wherein the content percentage of indium in the second oxide semiconductor
layer is higher than the content percentage of indium in the first oxide semiconductor
layer and the content percentage of indium in the third oxide semiconductor layer, and
20 wherein an absorption coefficient of a channel formation region in the oxide
semiconductor stacked film, which is measured by the CPM, is lower than or equal to $3 \times 10^{-3}/\text{cm}$ in an energy range of 1.5 eV to 2.3 eV.

14. The semiconductor device according to claim 13, wherein the second oxide
25 semiconductor layer includes a crystal part whose c-axis is substantially perpendicular
to a surface of the oxide semiconductor stacked film.

15. The semiconductor device according to claim 13, wherein in the second
oxide semiconductor layer, the content percentage of indium is higher than the content
30 percentage of gallium.

16. The semiconductor device according to claim 13, wherein the second oxide

semiconductor layer has a stacked-layer structure.

17. The semiconductor device according to claim 13, wherein the conductivity of the second oxide semiconductor layer is higher than the conductivity of the first
5 oxide semiconductor layer and the conductivity of the third oxide semiconductor layer.

18. The semiconductor device according to claim 13 further comprising an oxide insulating film over the pair of electrode layers and the oxide semiconductor stacked film.